

[illegible]

A cross-sectional view of a semiconductor device. It shows a substrate with a top layer 101, a middle layer 101a, and a bottom layer 102. A trench structure 106 is formed in the top layer 101, extending through the middle layer 101a and reaching the bottom layer 102. The trench has a complex, stepped profile.

A cross-sectional view of a semiconductor device. A substrate 101 is shown with a layer 102 on top. A trench structure 106 is formed in the substrate 101, extending through layer 102. A sub-layer 101a is located at the bottom of the trench 106.

FIG. 2

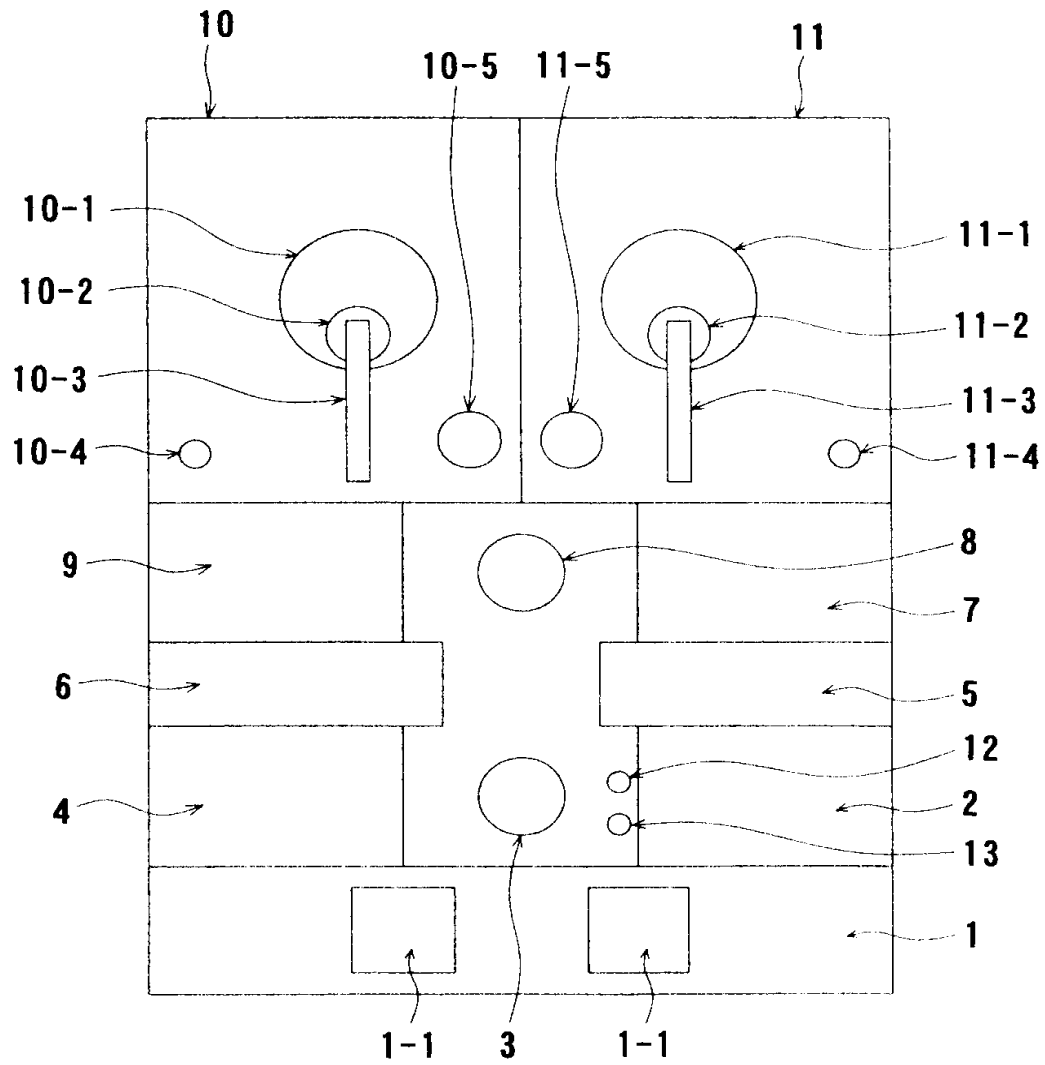


FIG. 3

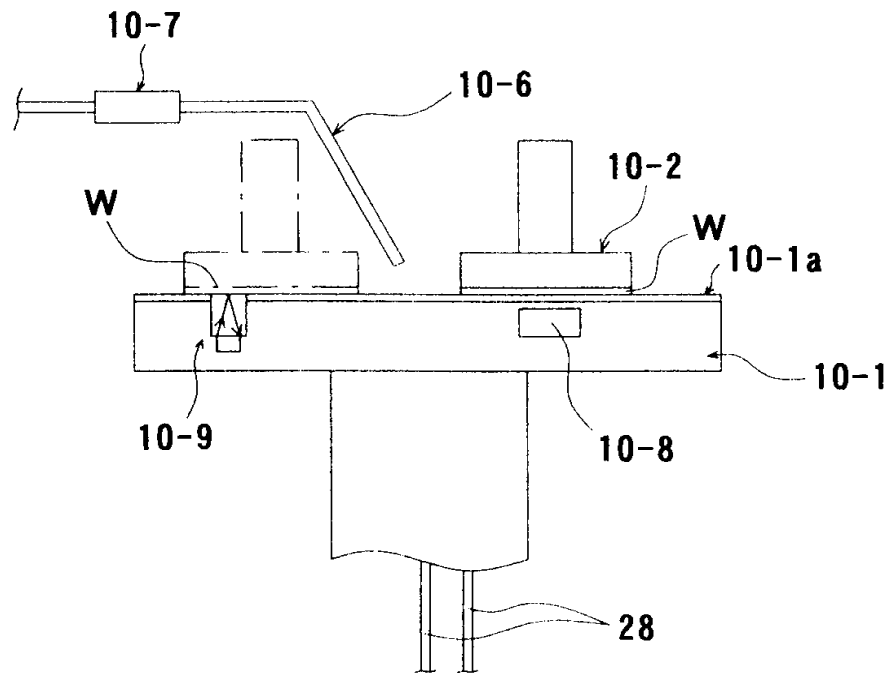


FIG. 4

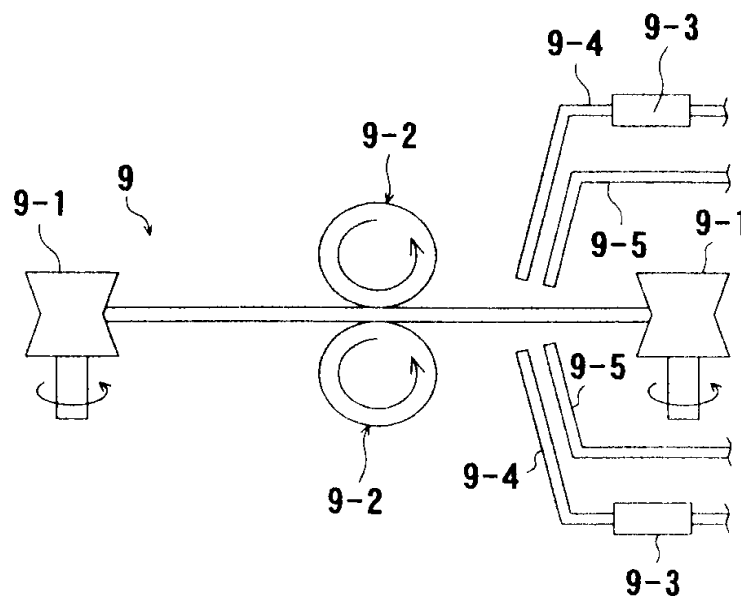


FIG. 5

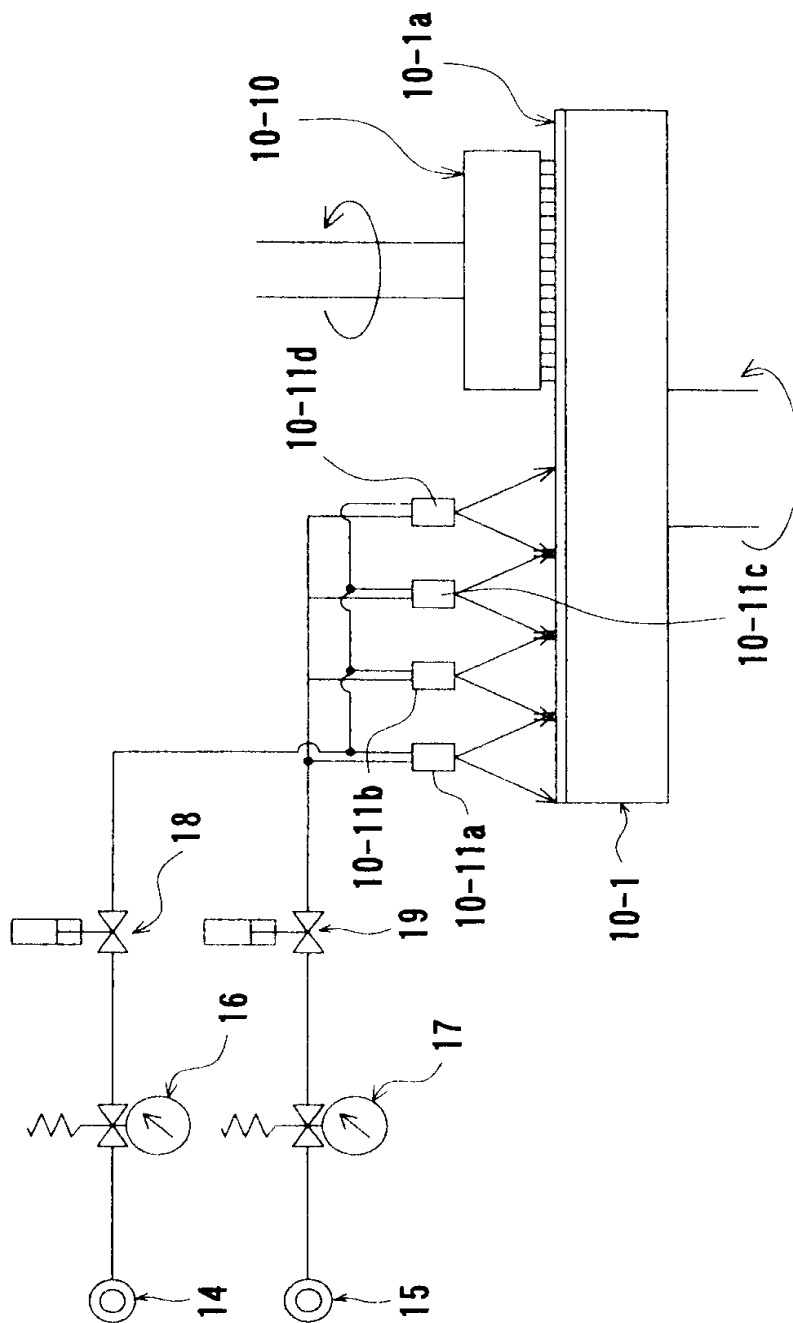


FIG. 6A

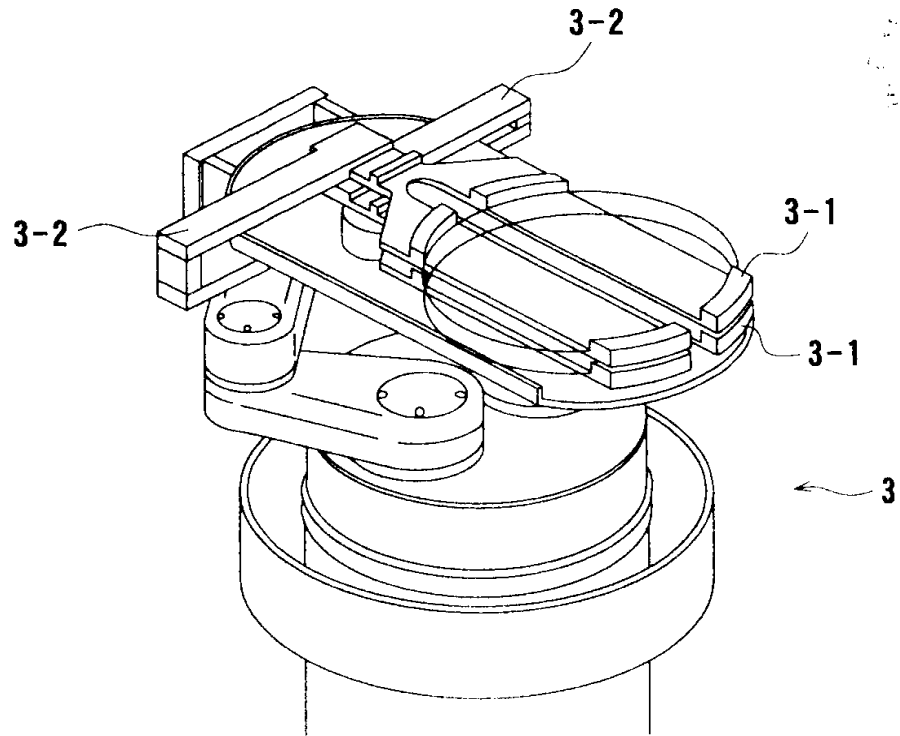


FIG. 6B

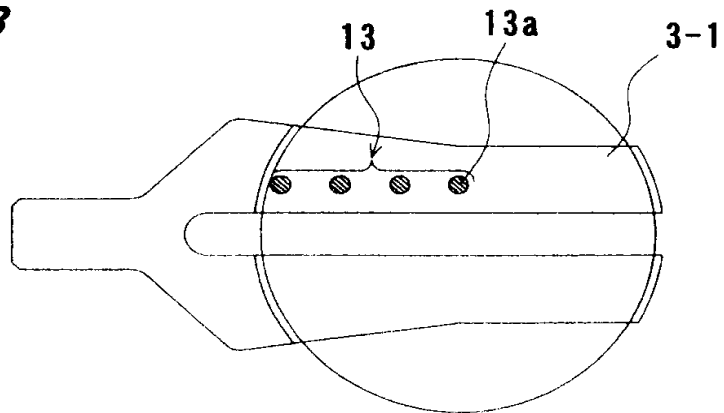


FIG. 6C



FIG. 7

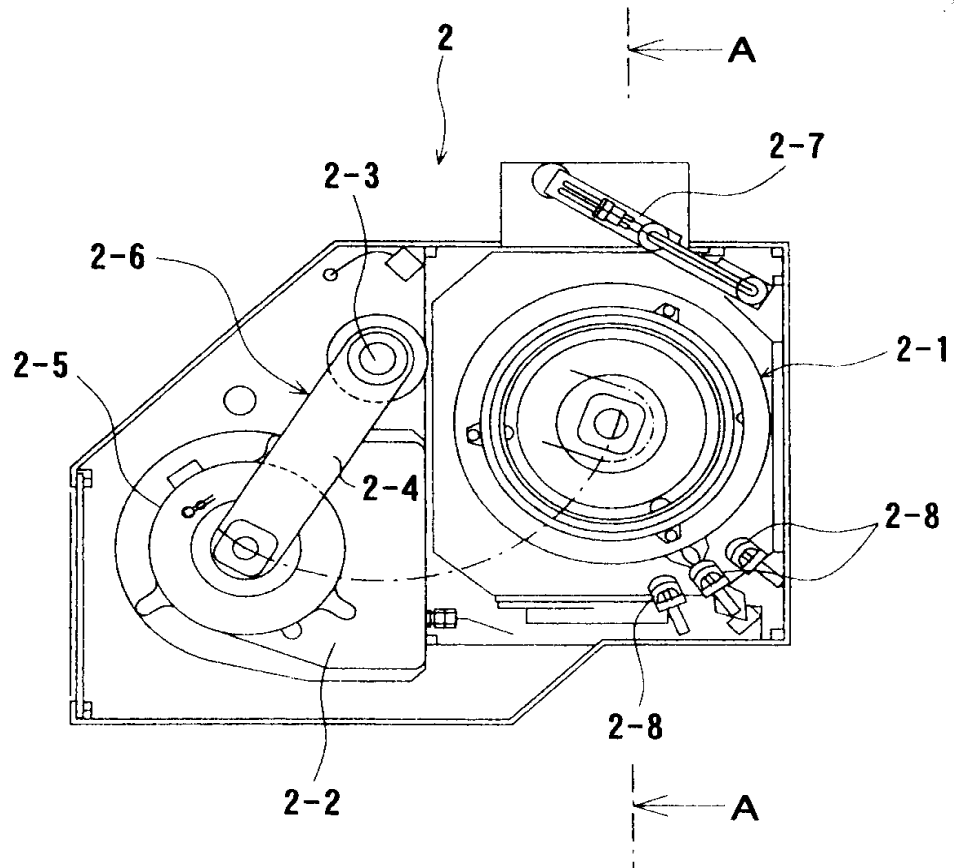
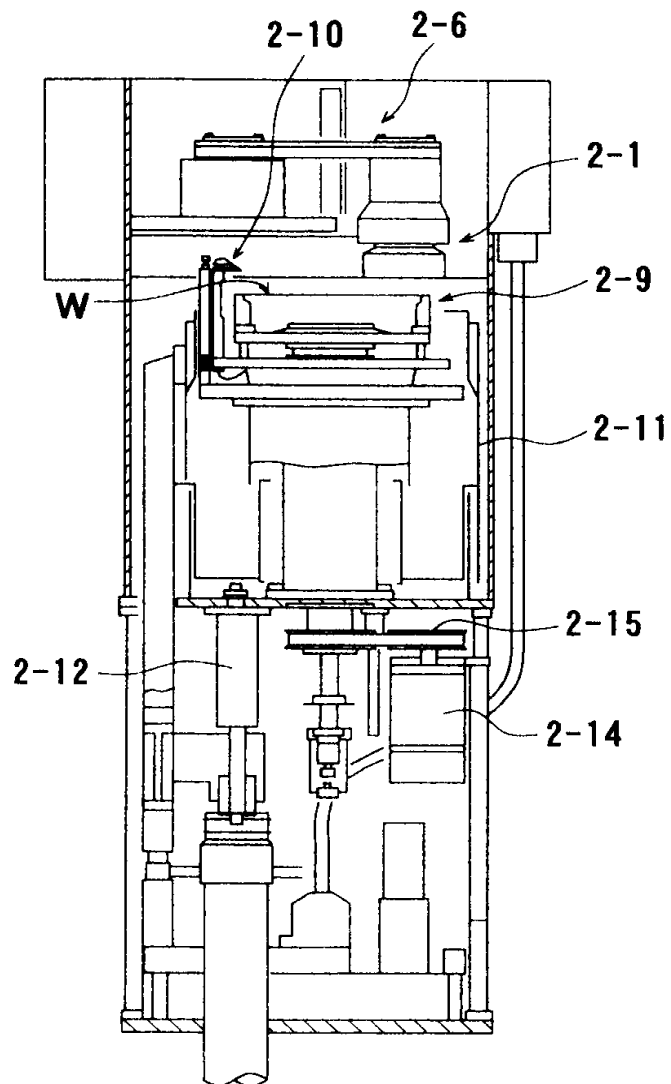


Figure 1 consists of 12 scatter plots, labeled (a) through (l), arranged in a 6x2 grid. Each plot shows the relationship between the number of children (N) on the x-axis and the number of children who are also parents (Np) on the y-axis. The plots are organized into two columns: the left column contains plots (a) through (f), and the right column contains plots (g) through (l). Each plot includes a regression line and a correlation coefficient (r). The y-axis for all plots is labeled 'Np' and the x-axis is labeled 'N'. The plots show varying degrees of positive correlation, with some having a shaded area around the regression line. The correlation coefficients (r) are as follows: (a) 0.88, (b) 0.88, (c) 0.88, (d) 0.88, (e) 0.88, (f) 0.88, (g) 0.88, (h) 0.88, (i) 0.88, (j) 0.88, (k) 0.88, (l) 0.88.



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FIG. 9

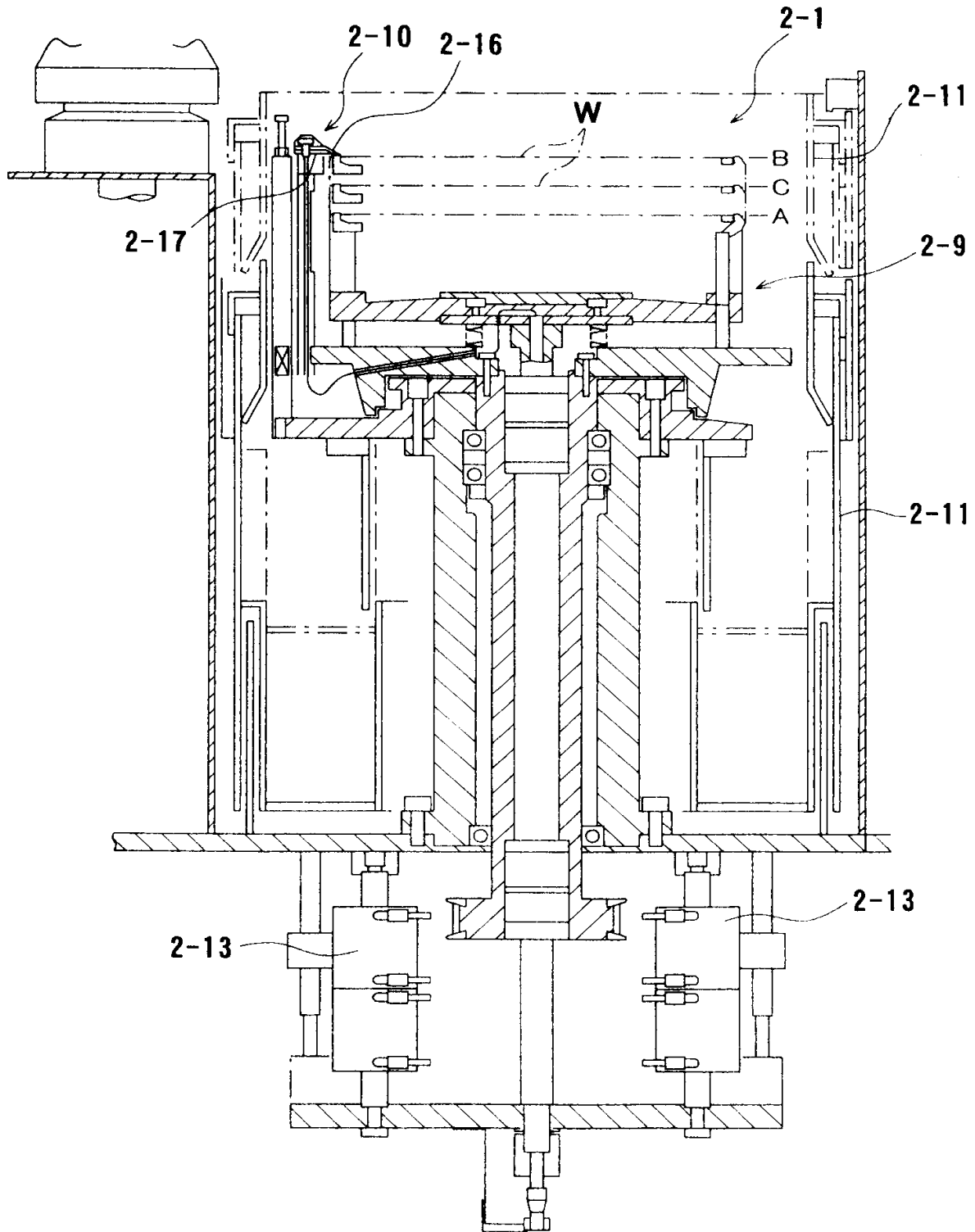


FIG. 10

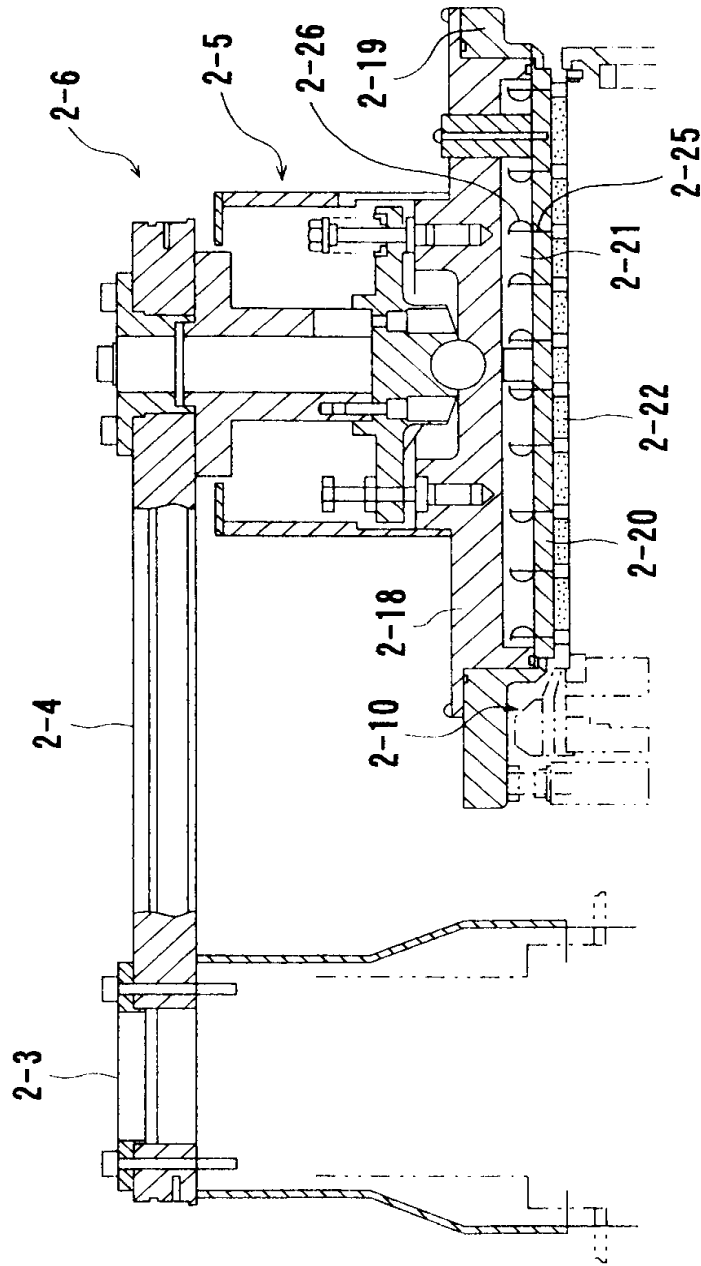


FIG. 11

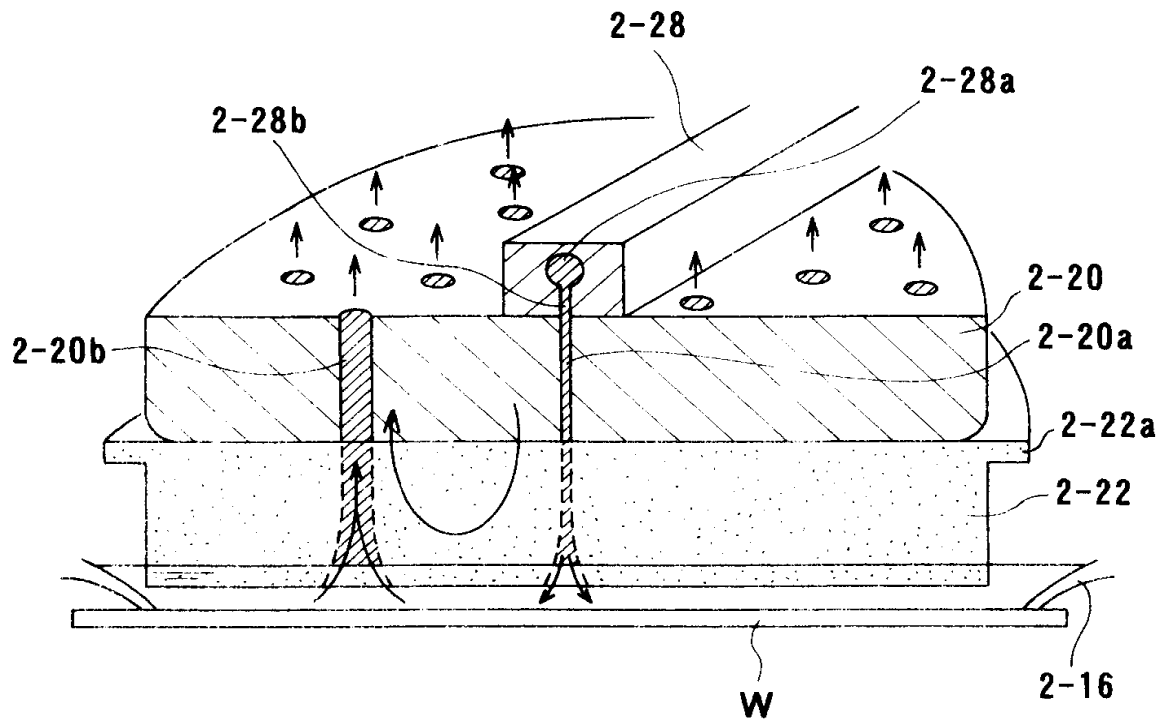


FIG. 13

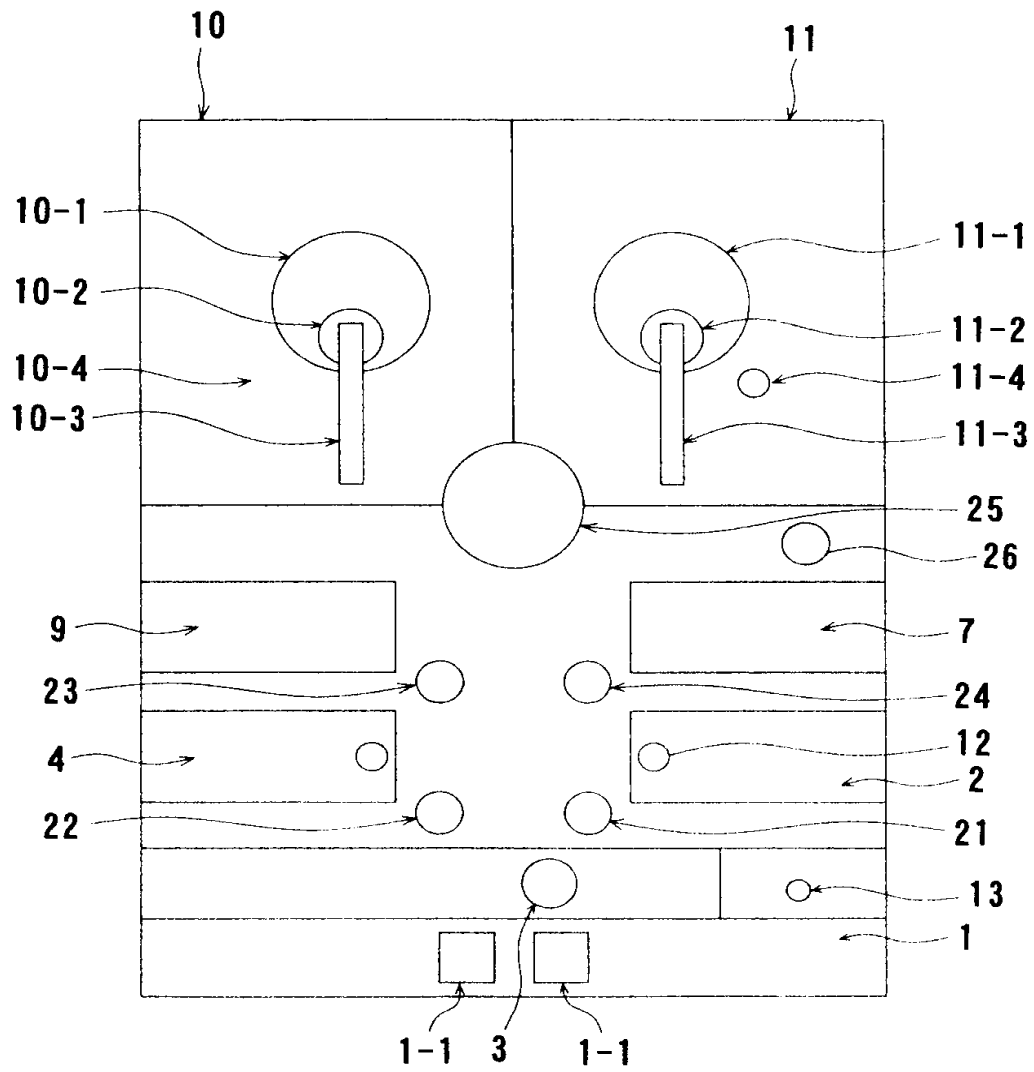


FIG. 14

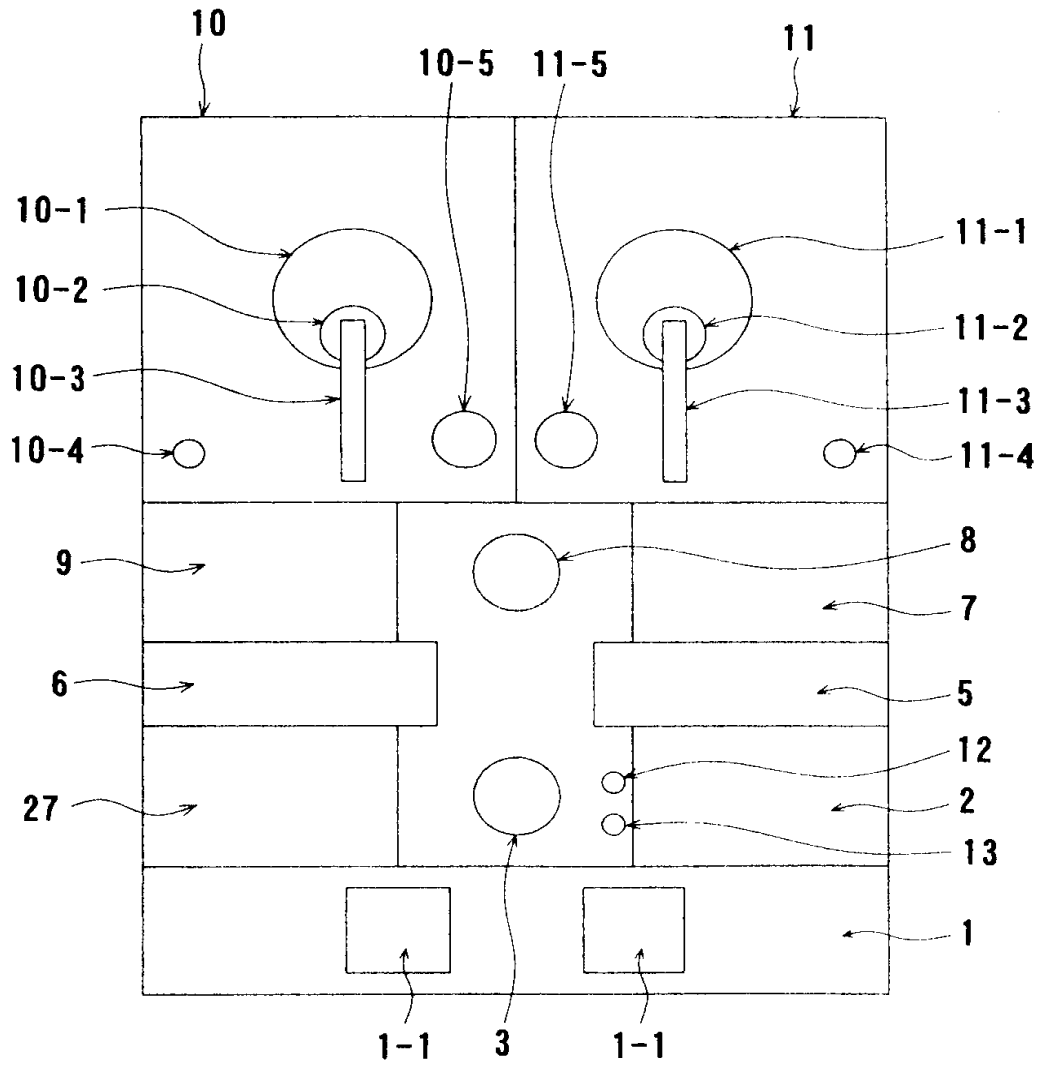


FIG. 15

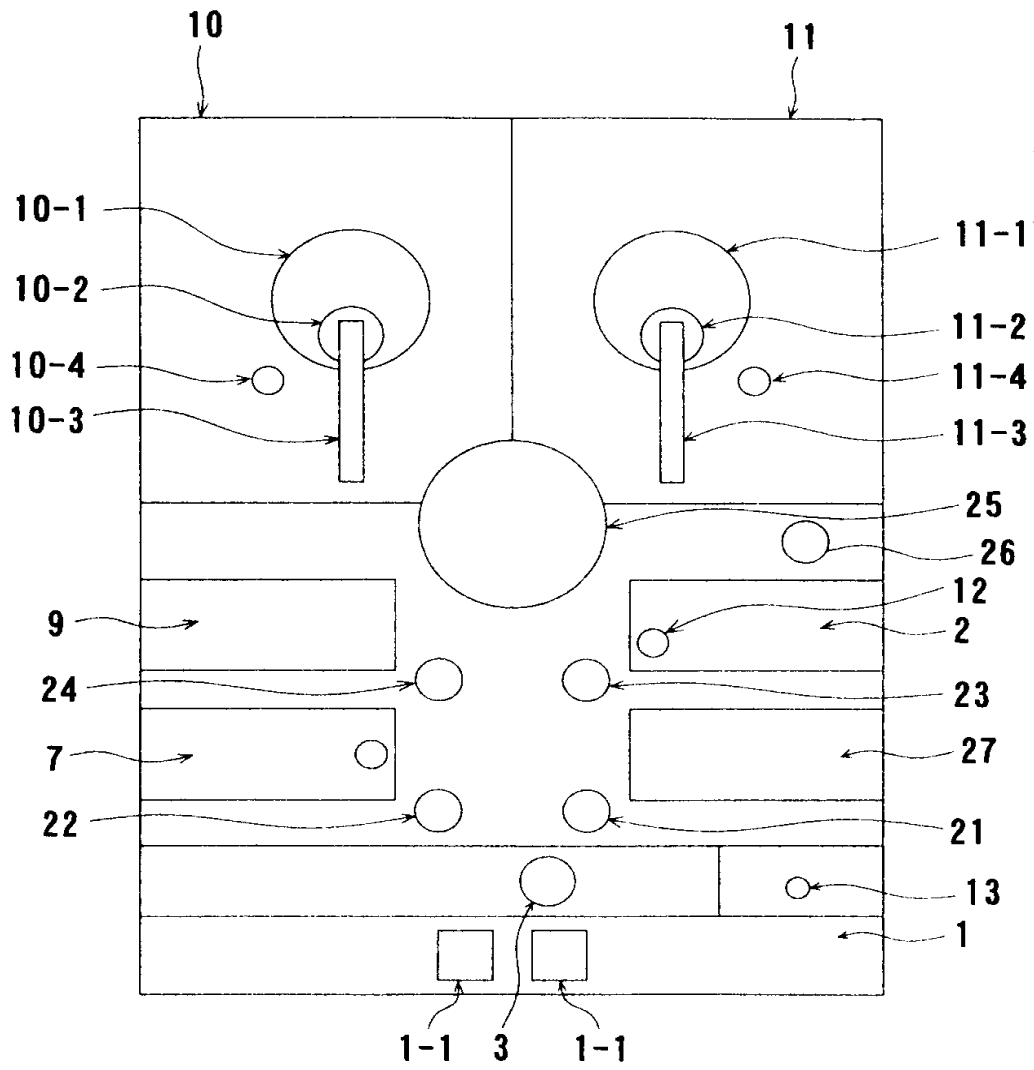


FIG. 16

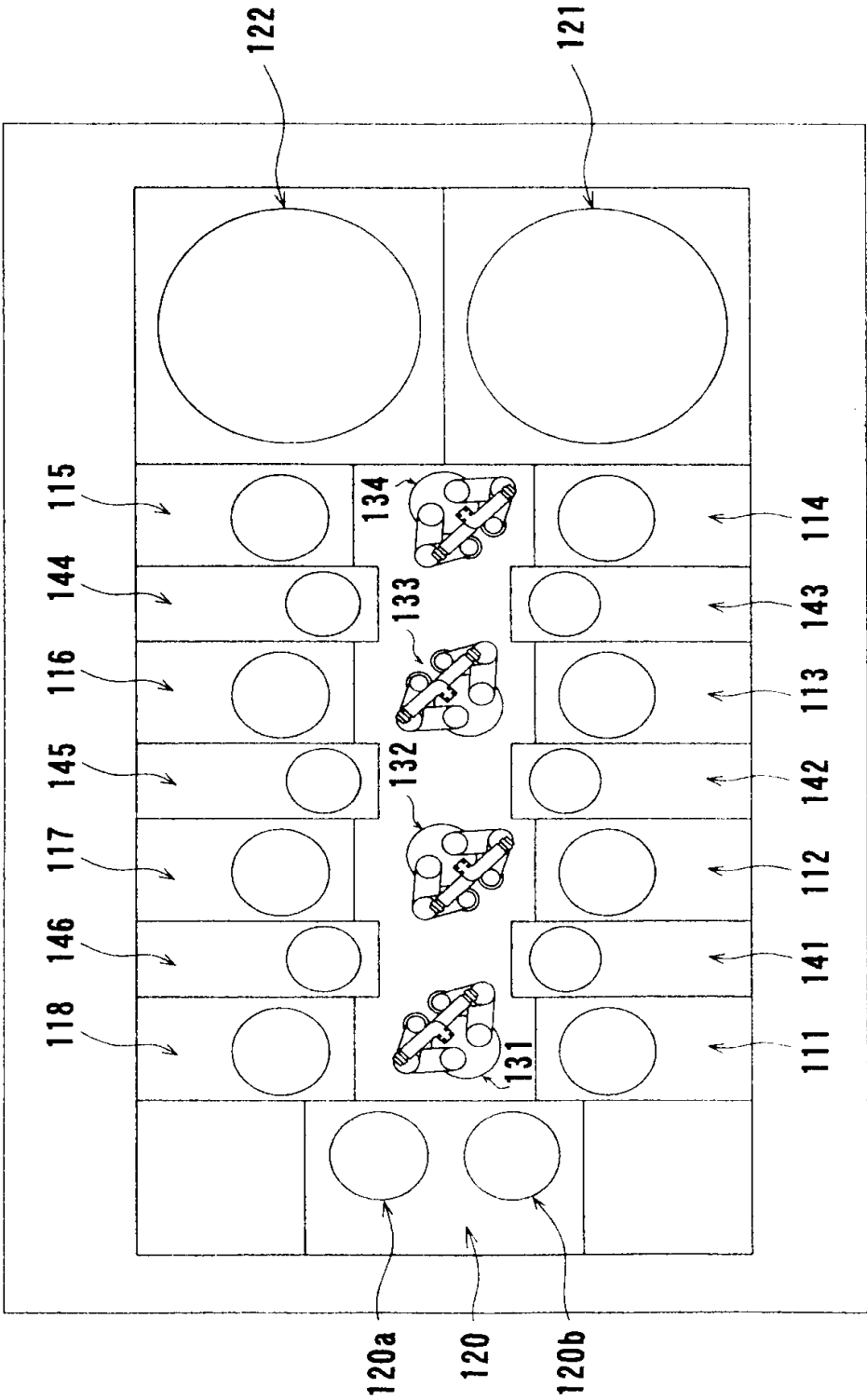


FIG. 17

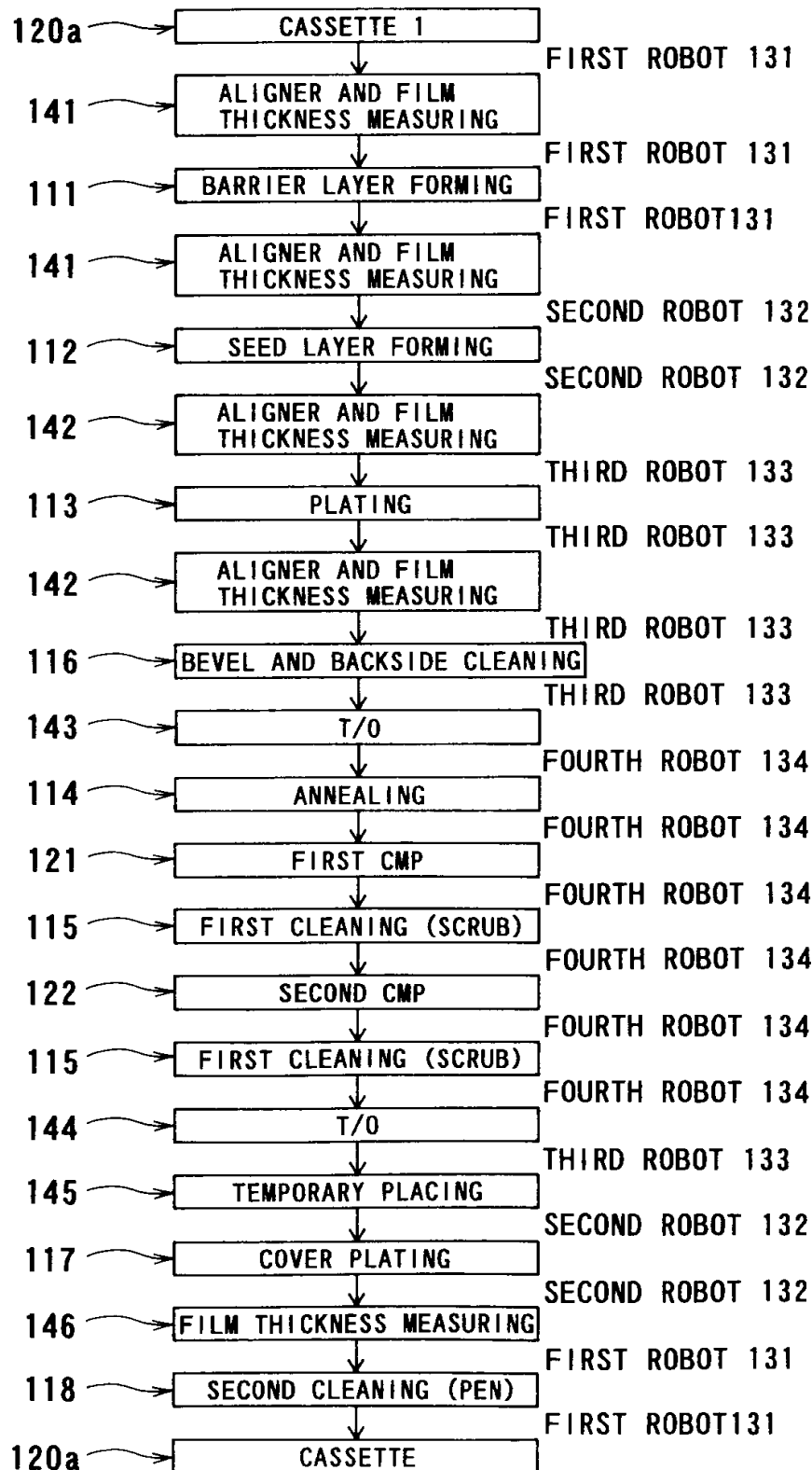


FIG. 18

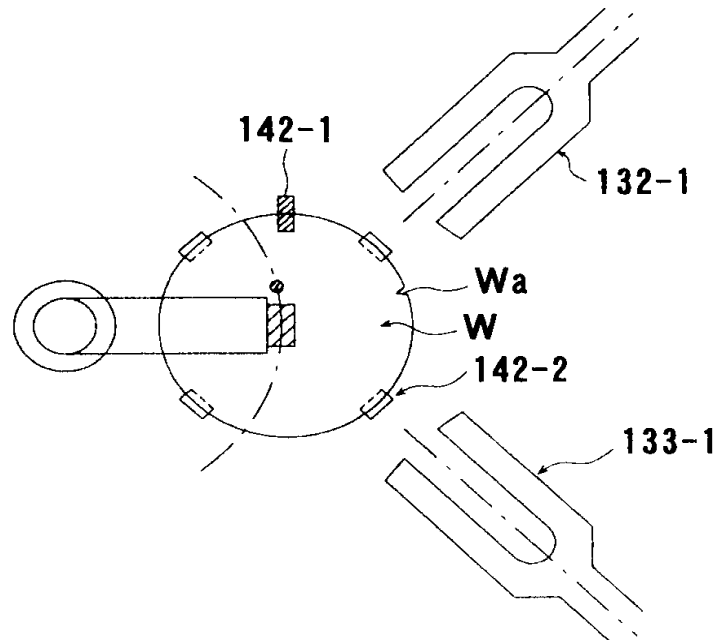


FIG. 19

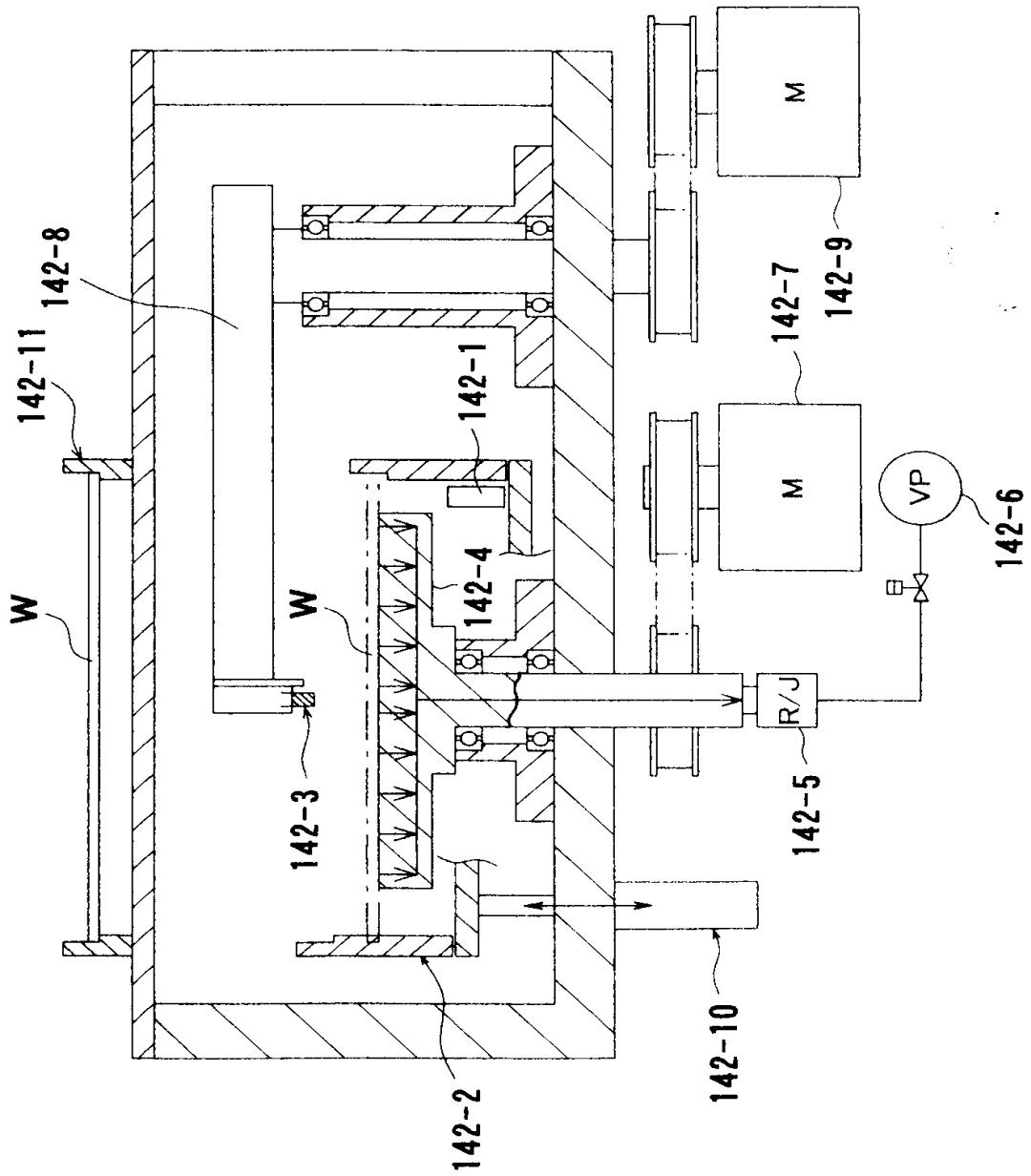


FIG. 20

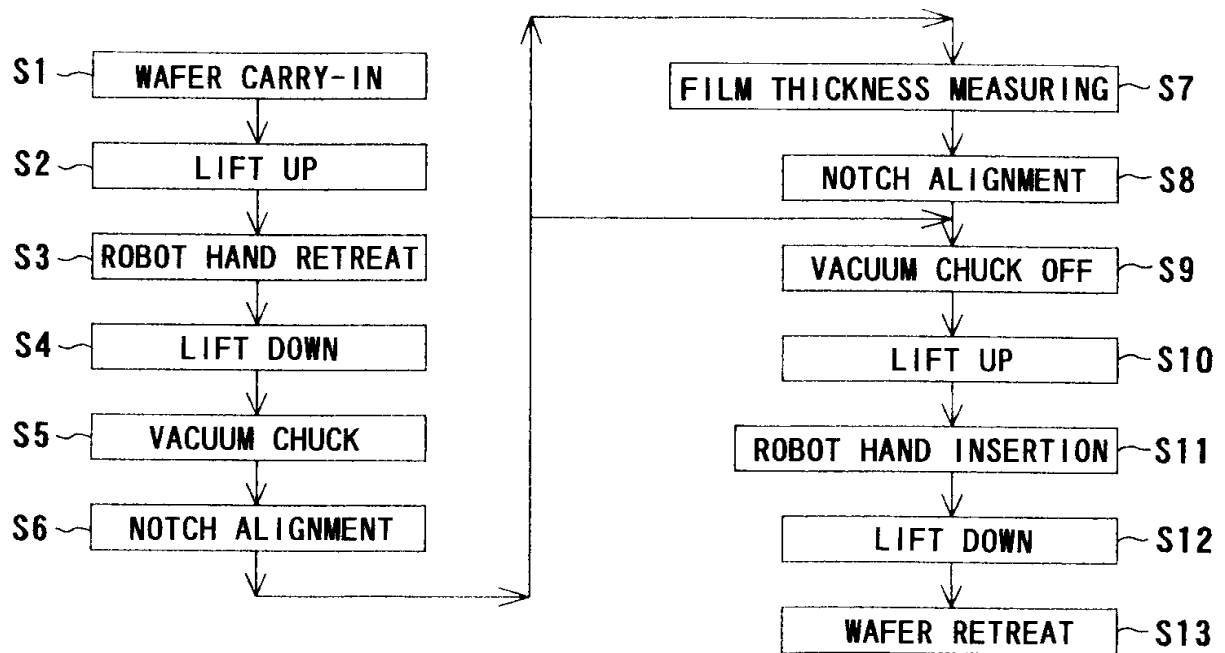


FIG. 21

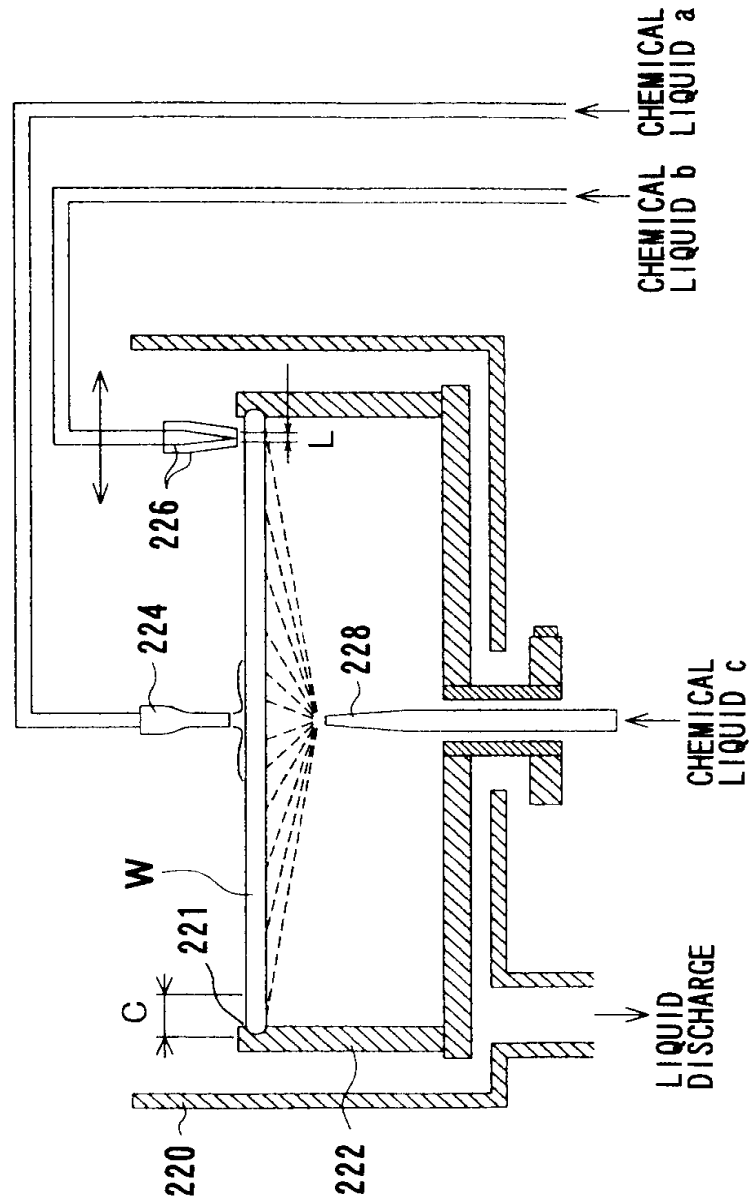


FIG. 22A

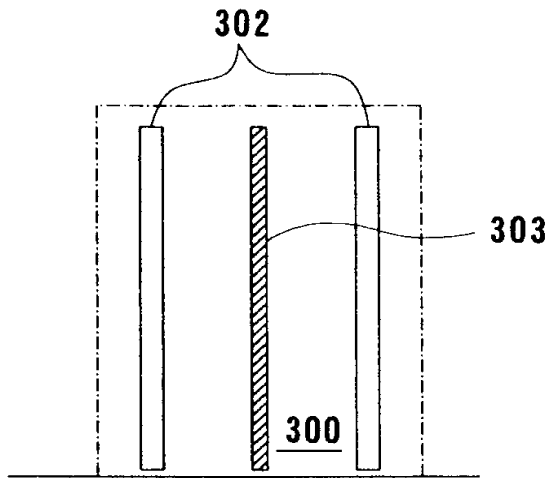


FIG. 22B

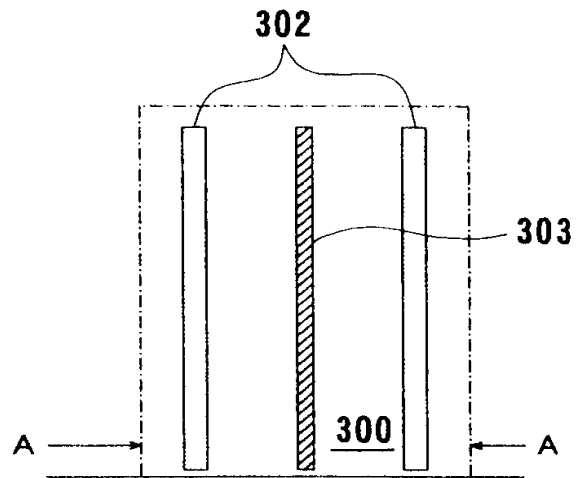


FIG. 22C

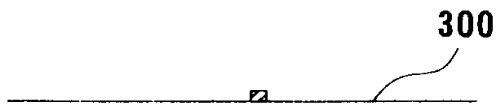


FIG. 22D

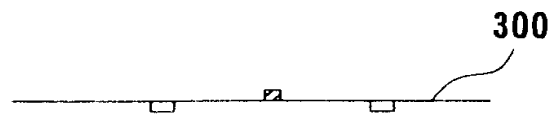


FIG. 23A

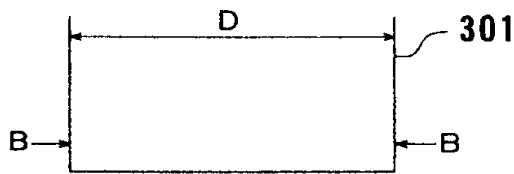


FIG. 23B

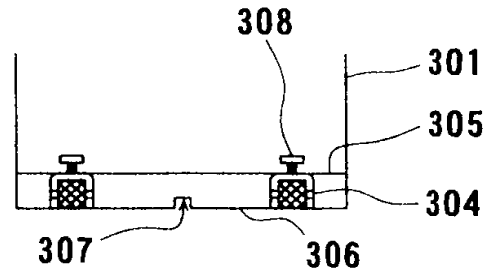


FIG. 24A

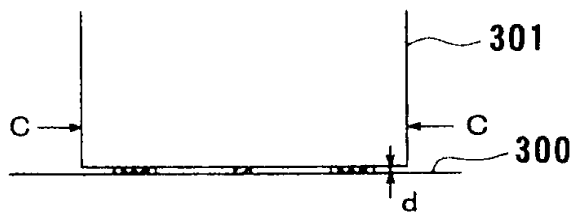


FIG. 24B

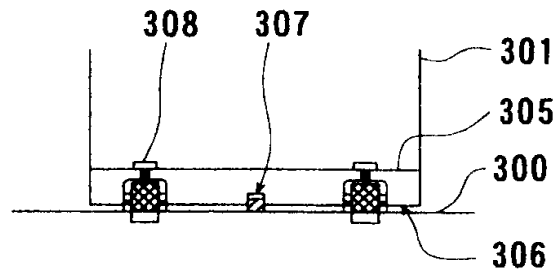


FIG. 25

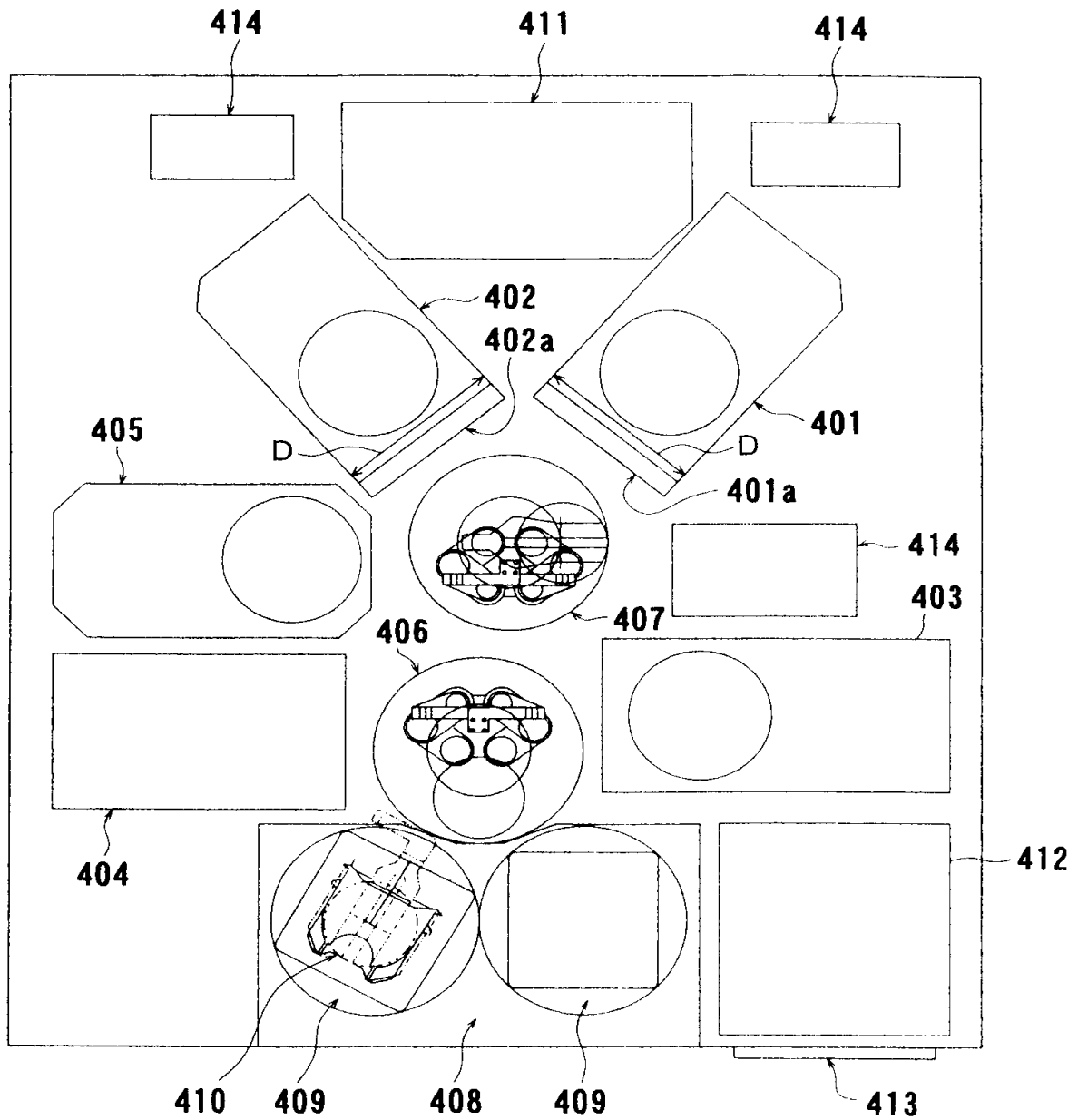


FIG. 26A

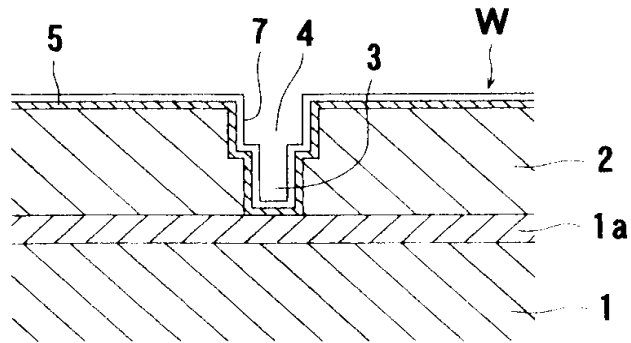


FIG. 26B

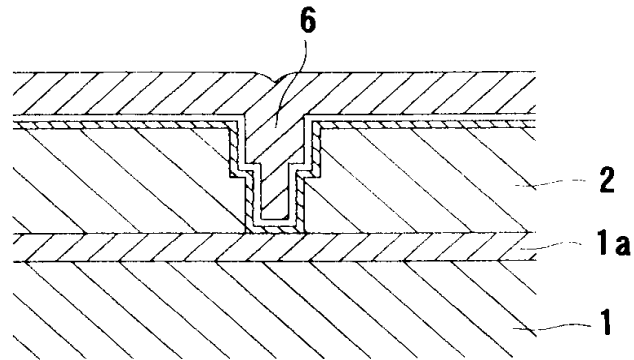


FIG. 26C

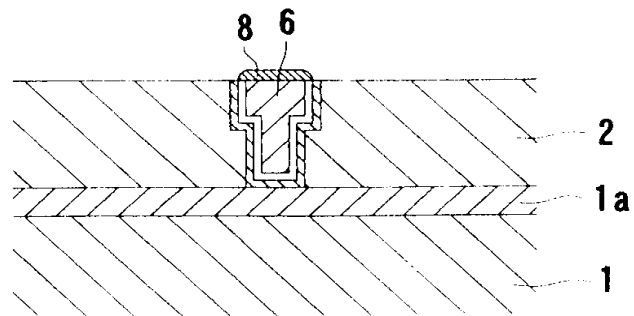


FIG. 27

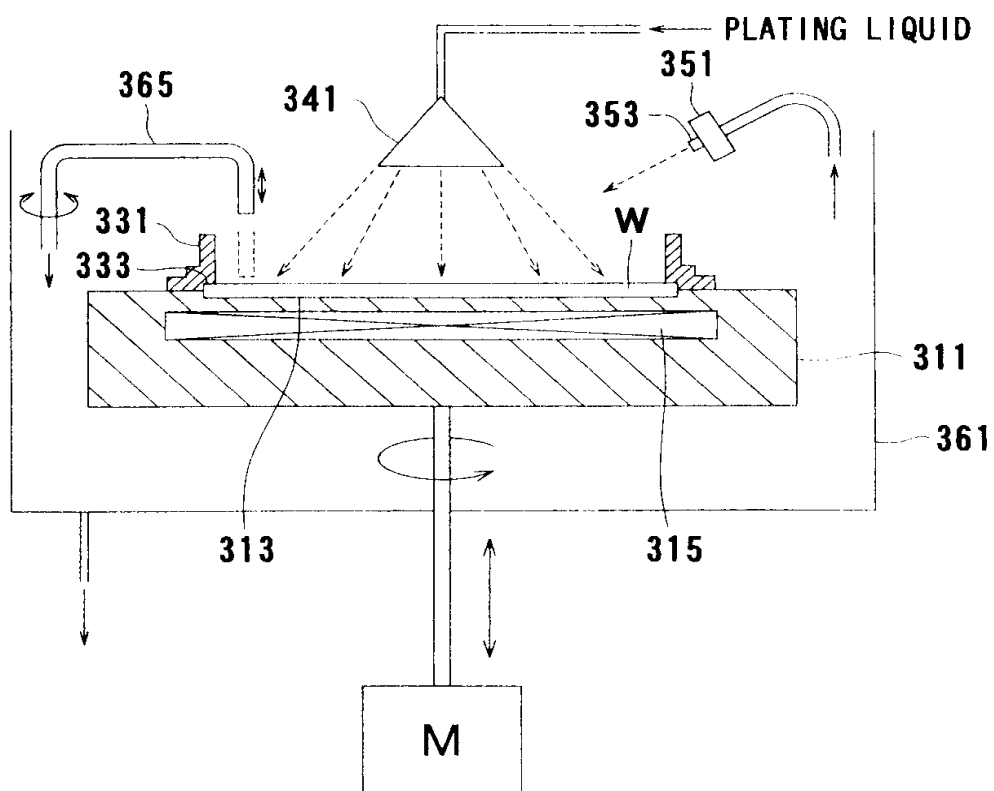
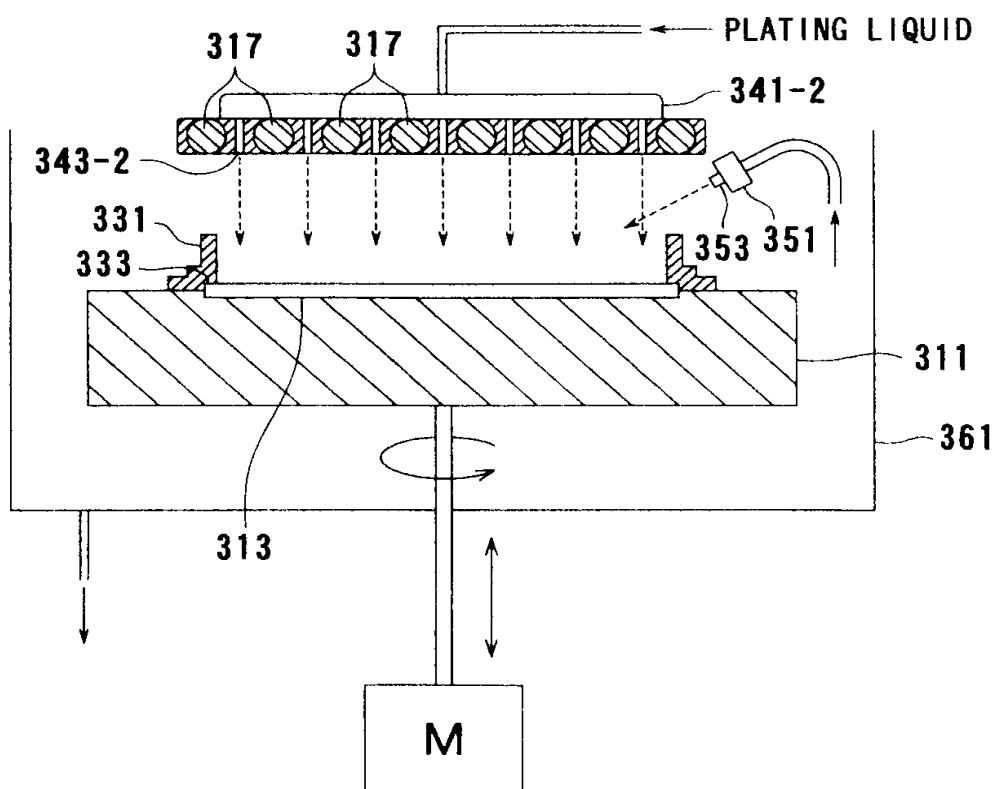


FIG. 28



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FIG. 29A

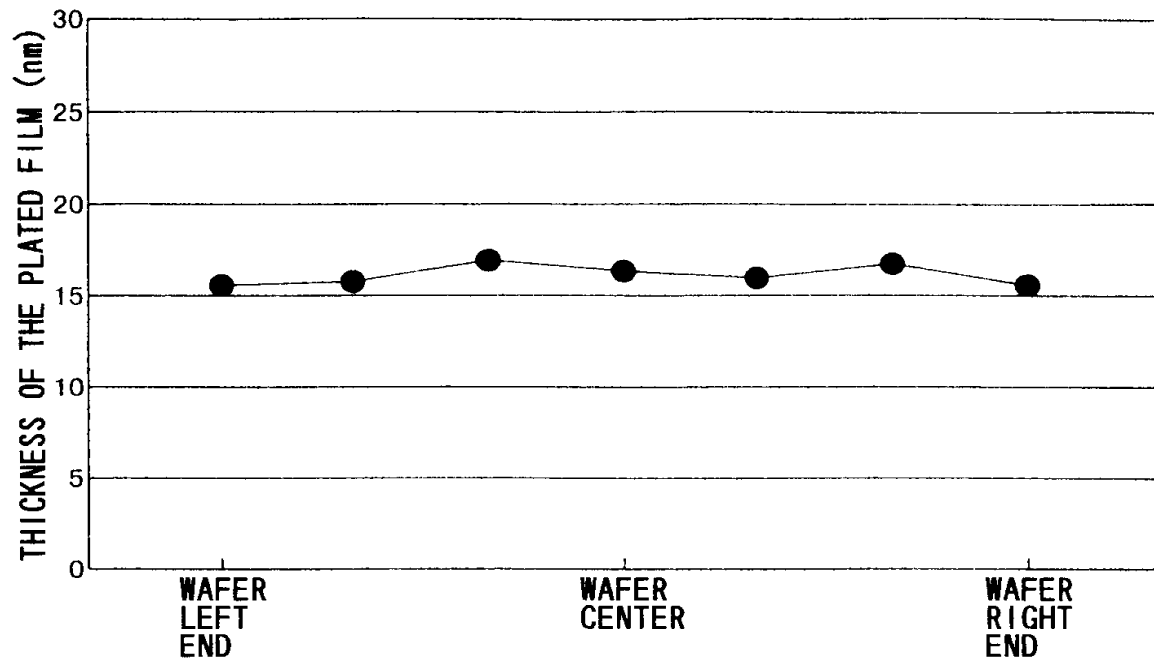


FIG. 29B

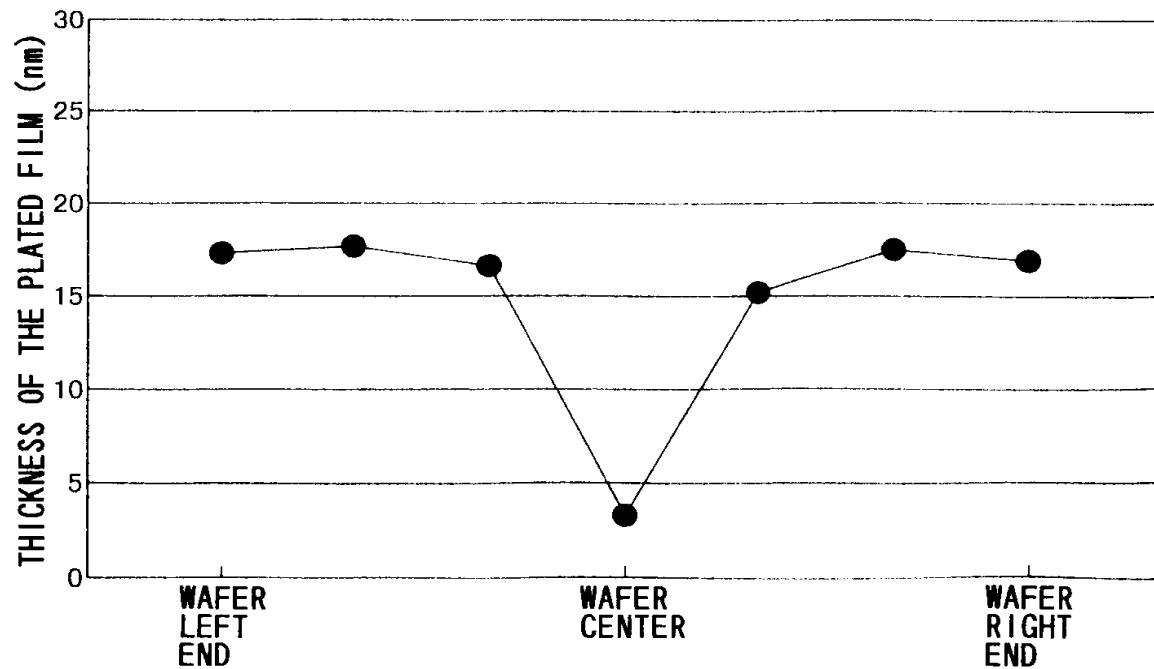


FIG. 30

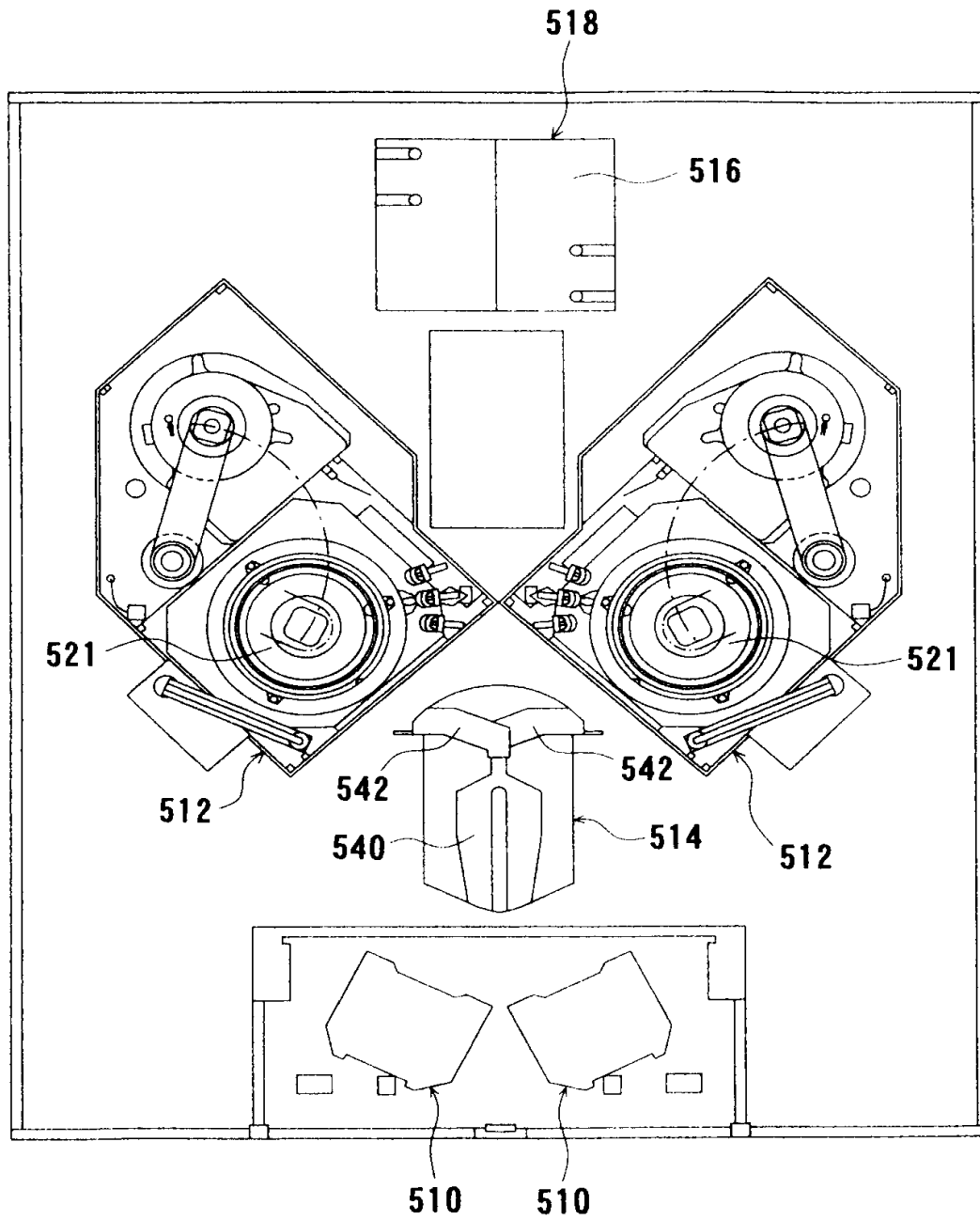


FIG. 31

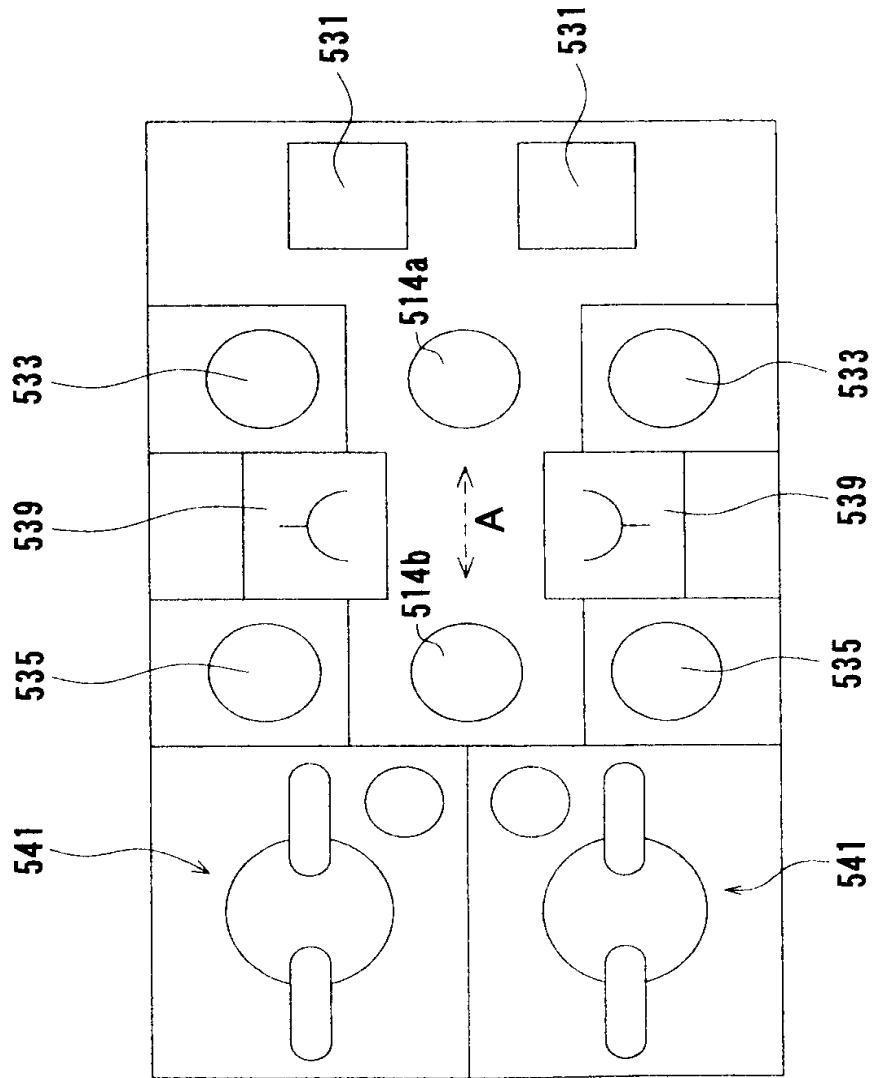


FIG. 32

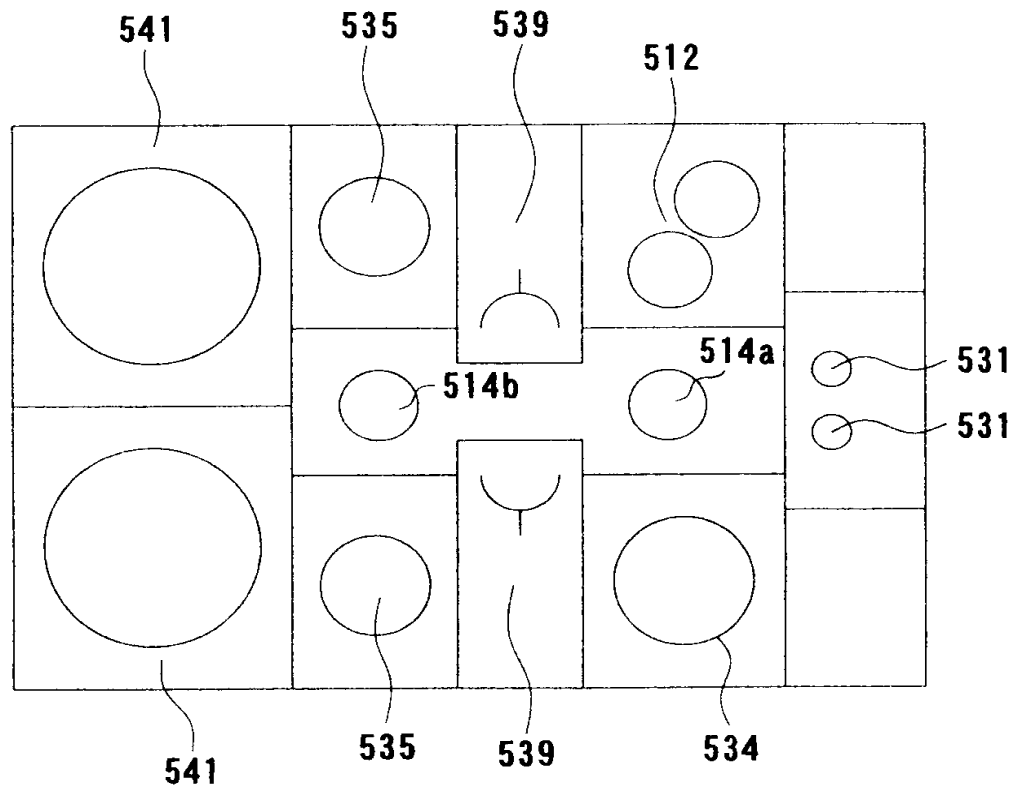


FIG. 33

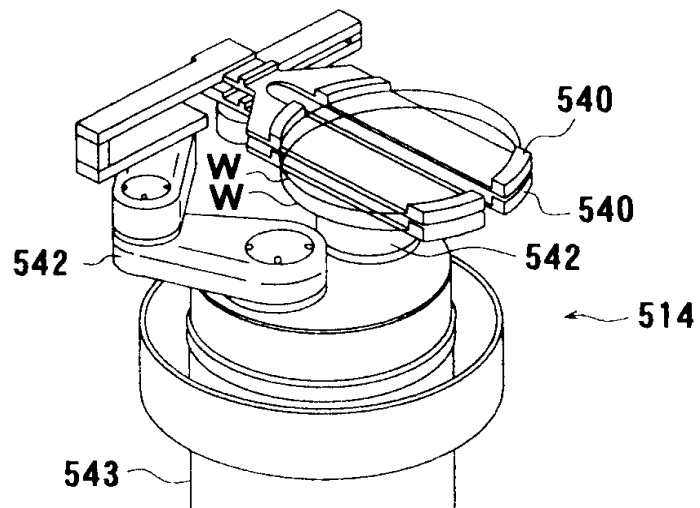


FIG. 34A

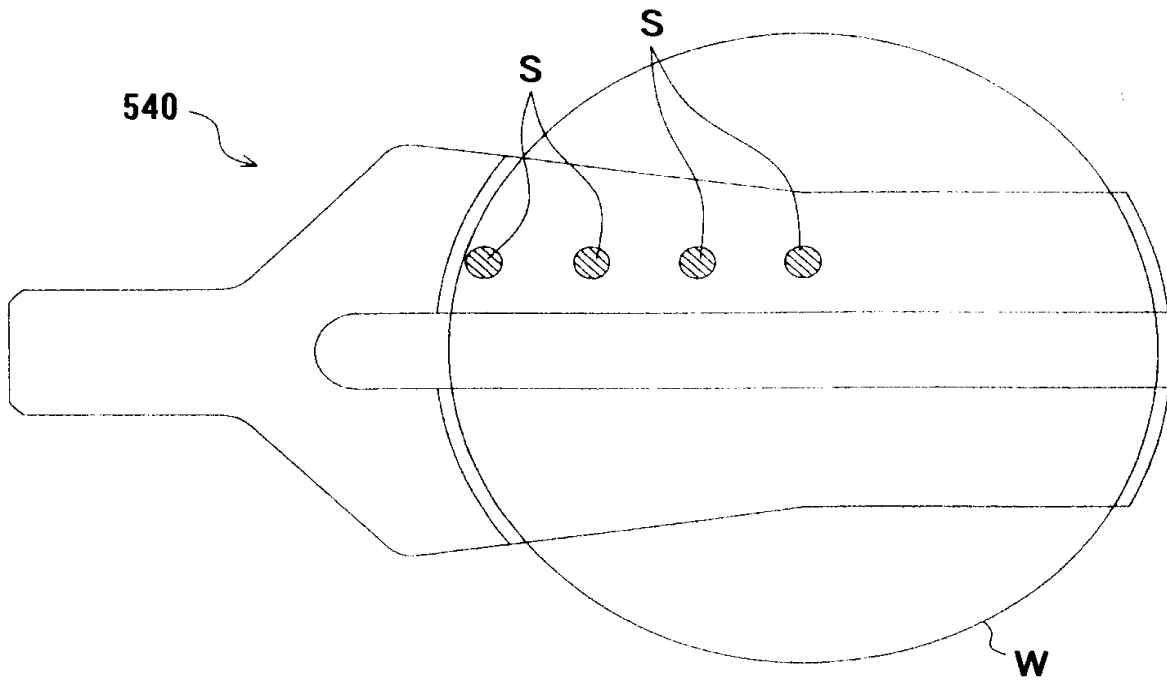


FIG. 34B

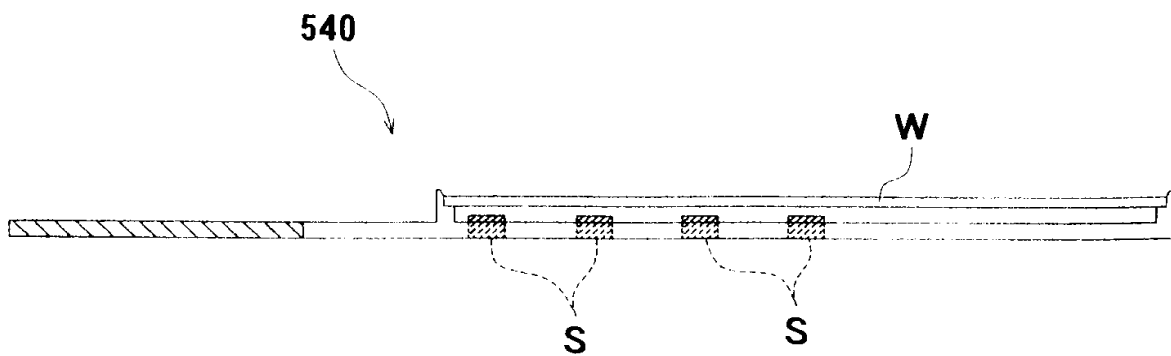


FIG. 35A

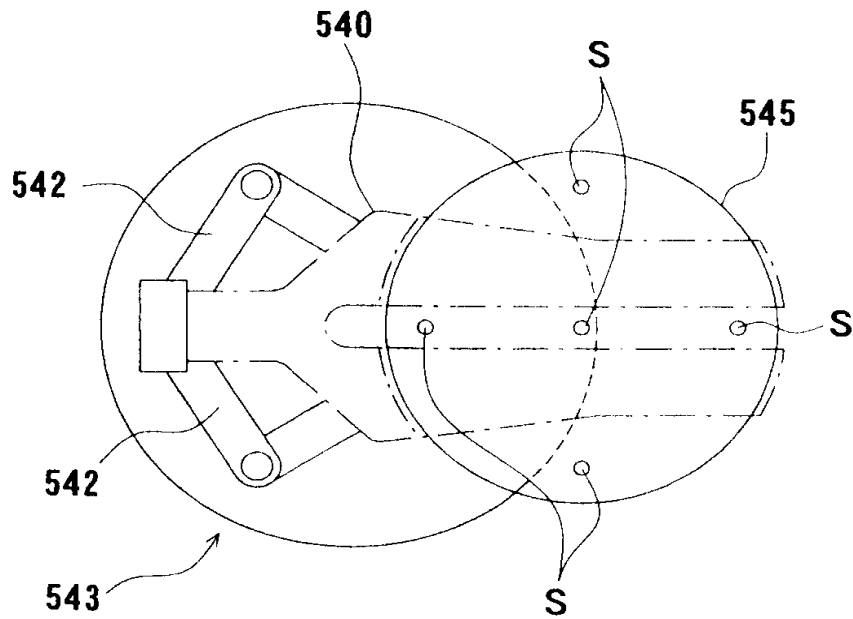


FIG. 35B

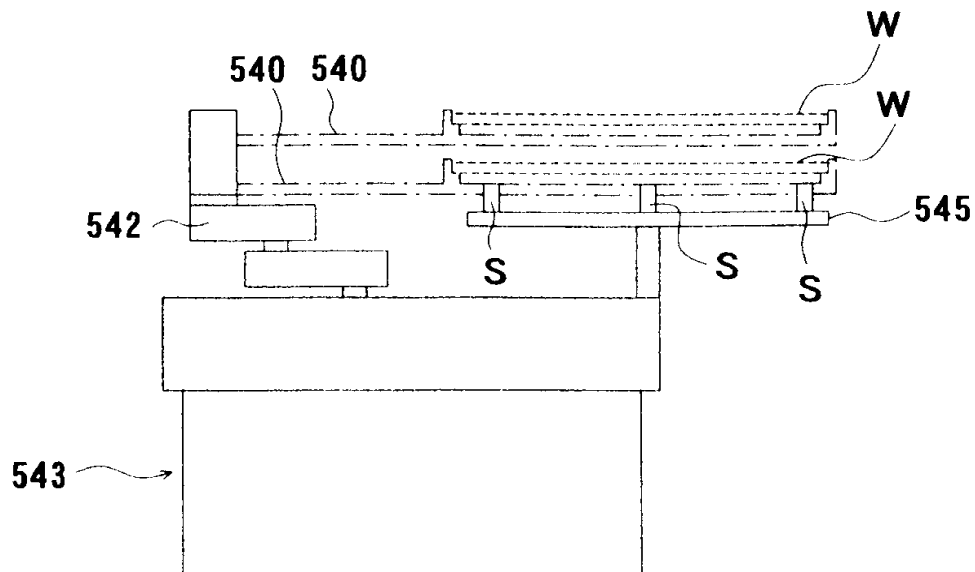


FIG. 36A

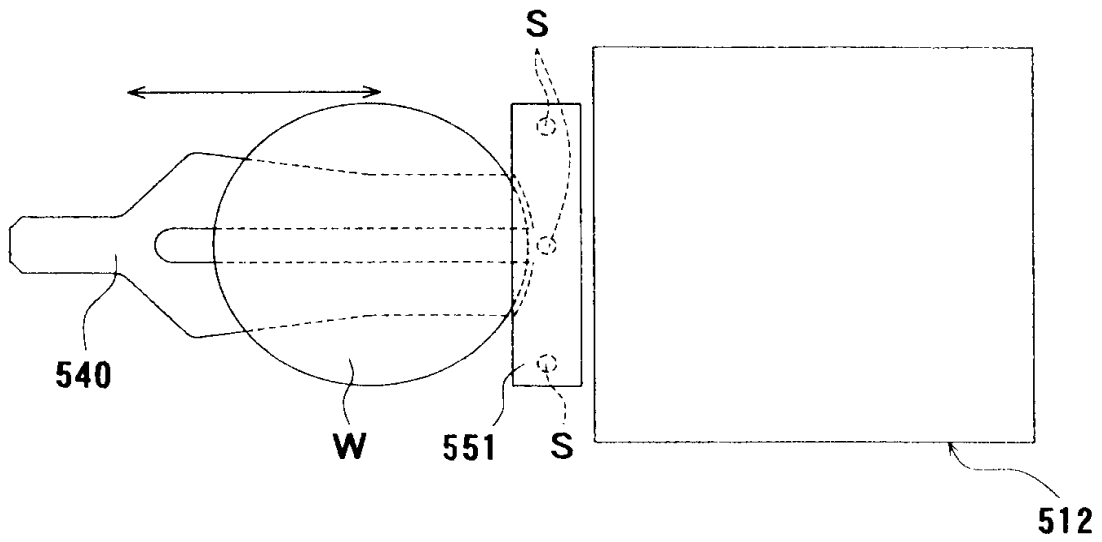


FIG. 36B

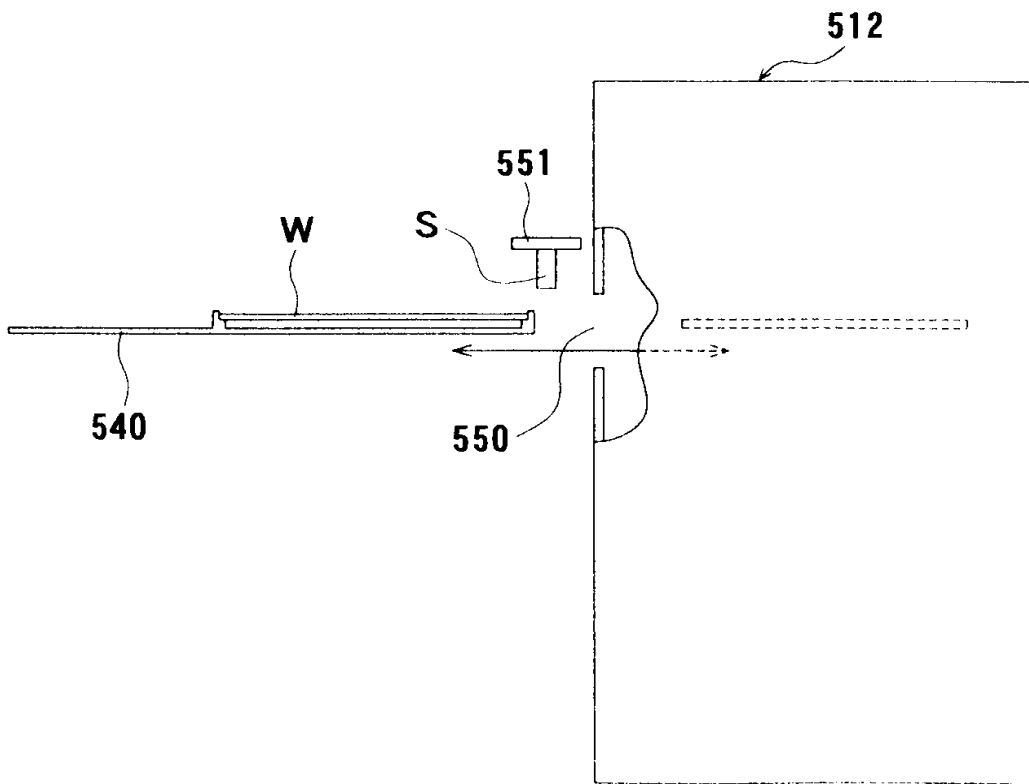


FIG. 37

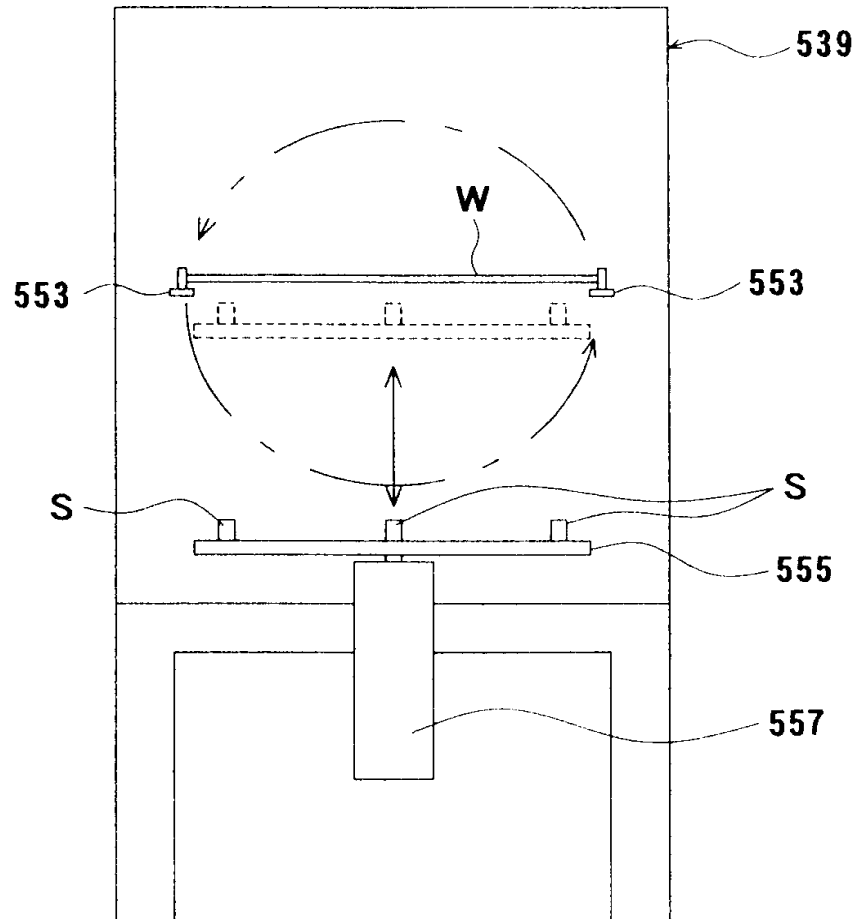


FIG. 38

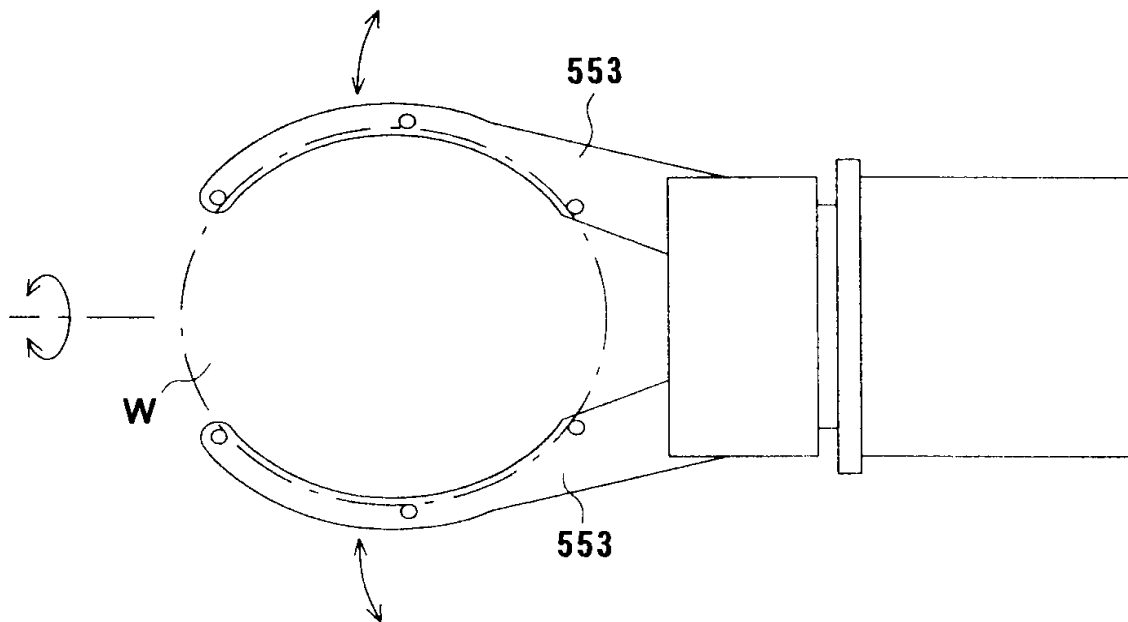


FIG. 39

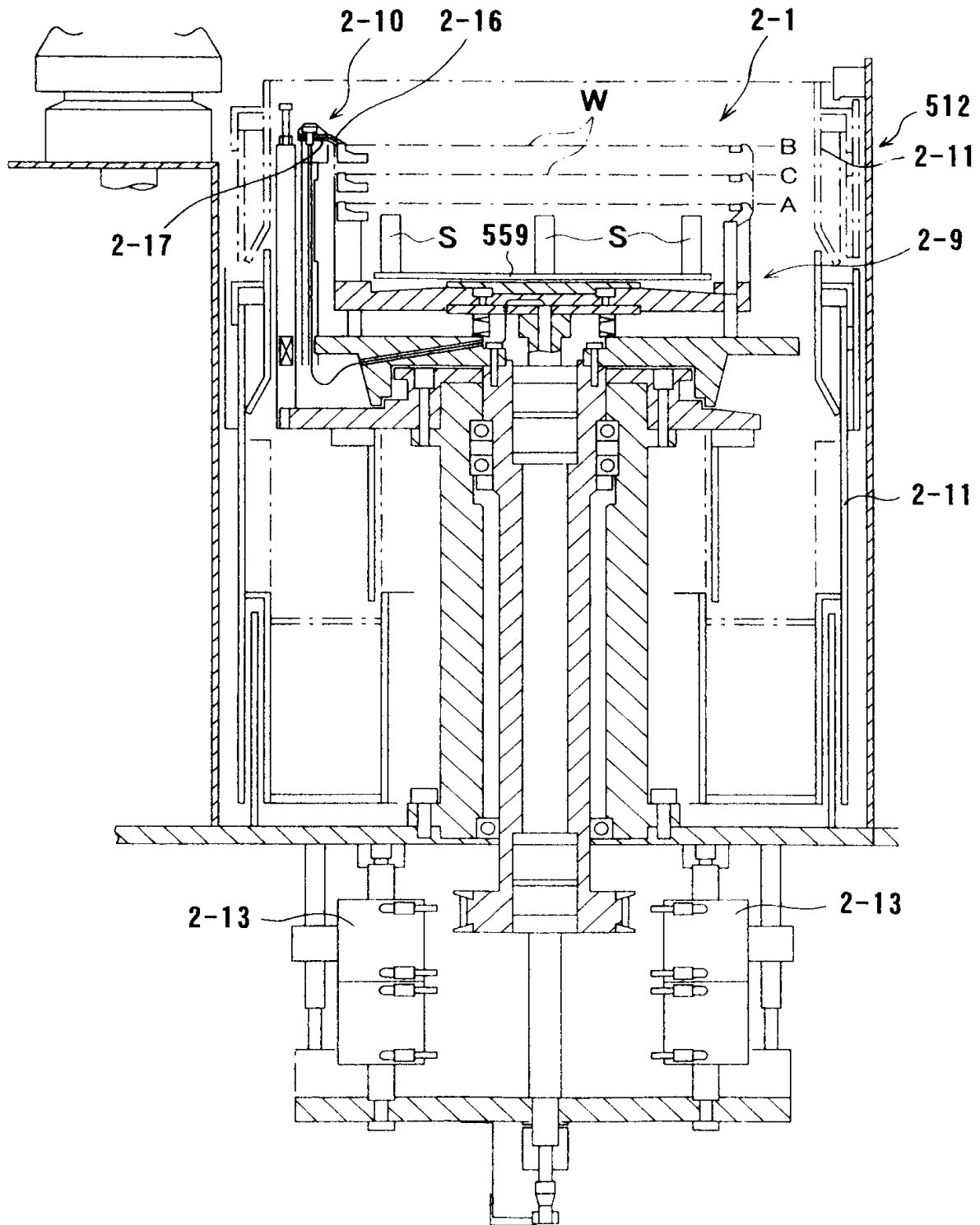


FIG. 40

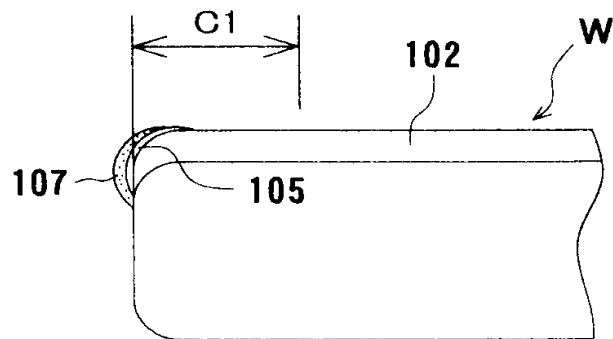


FIG. 41

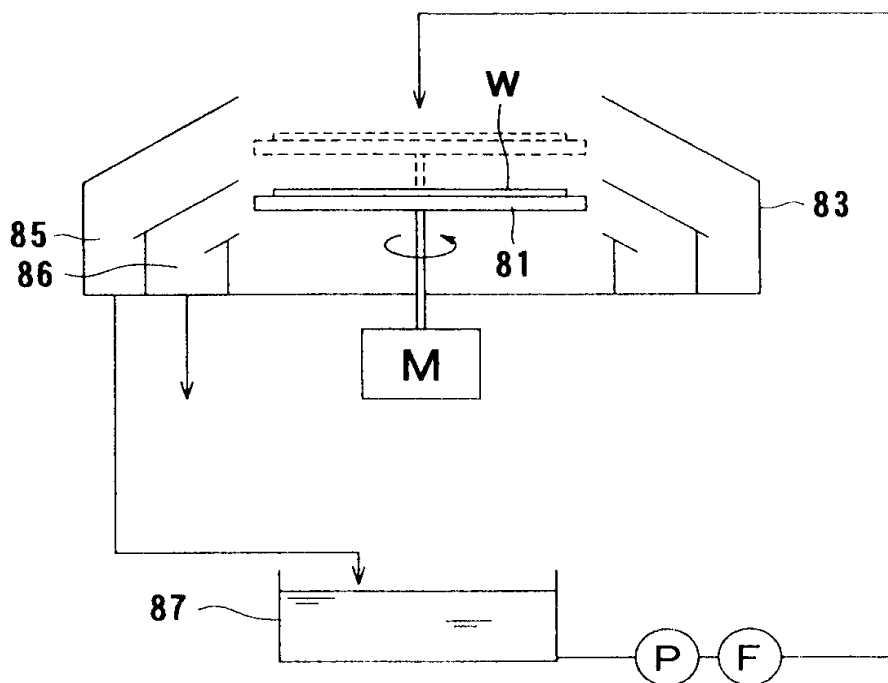


FIG. 42

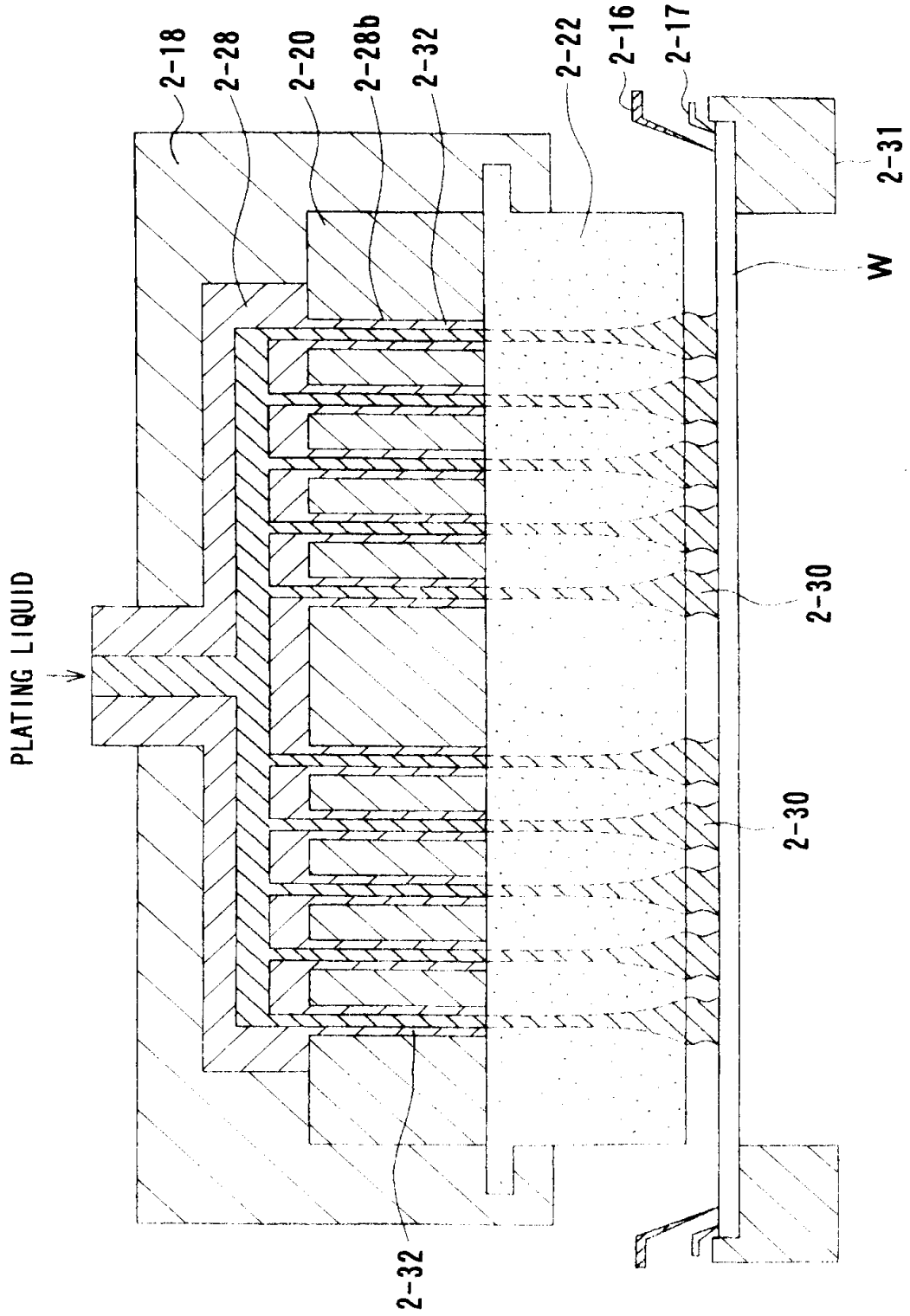
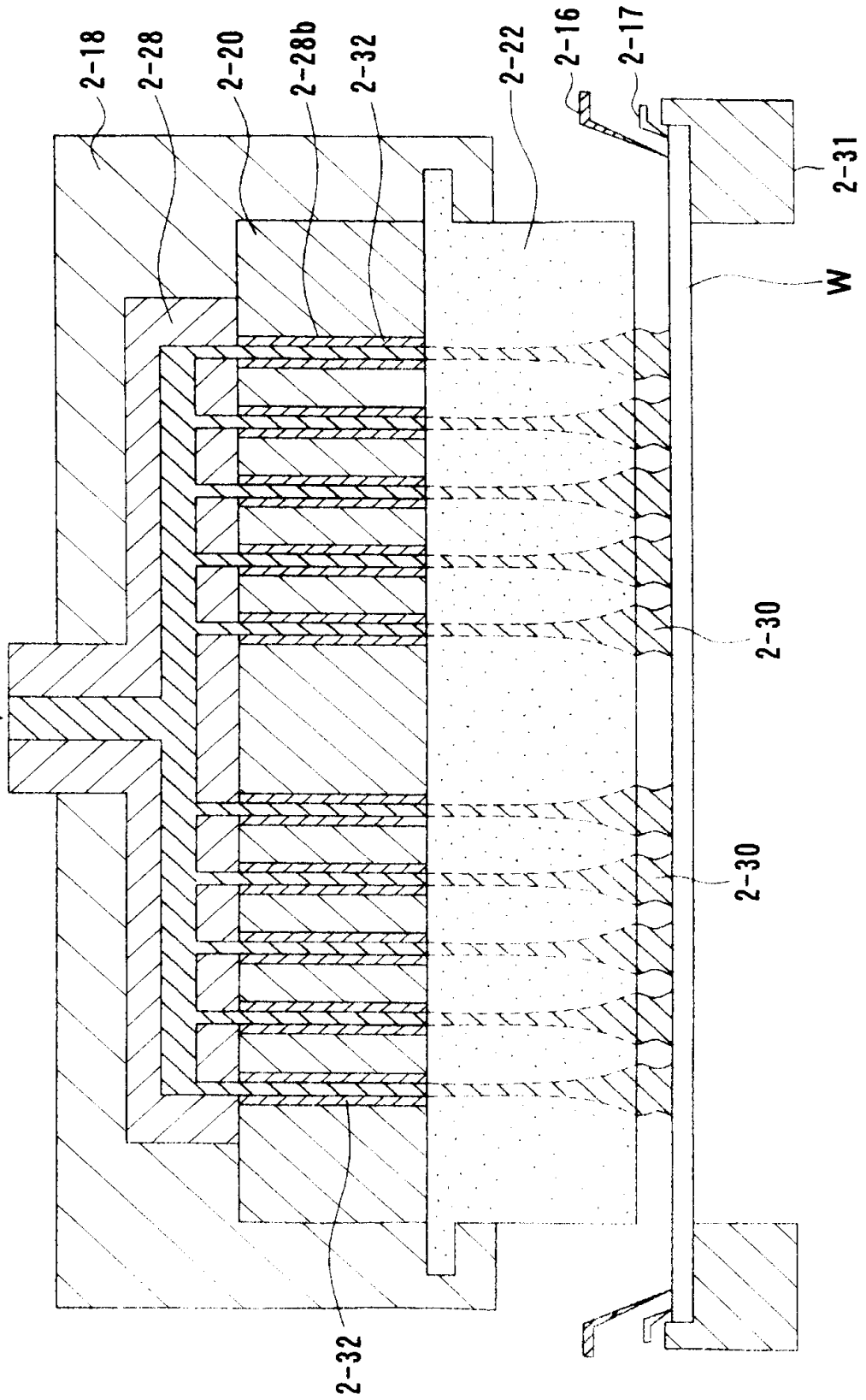


FIG. 43

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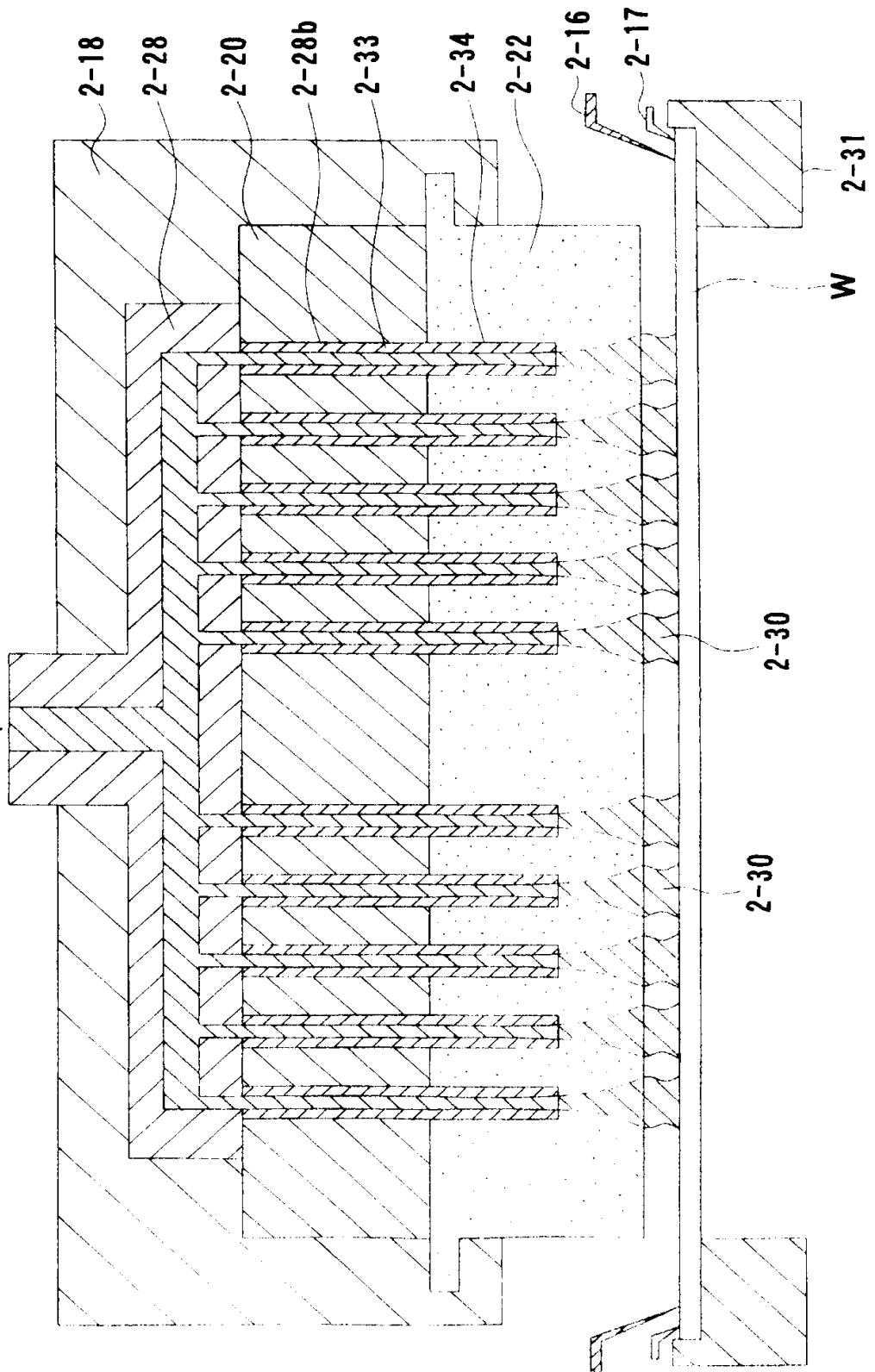


FIG. 45

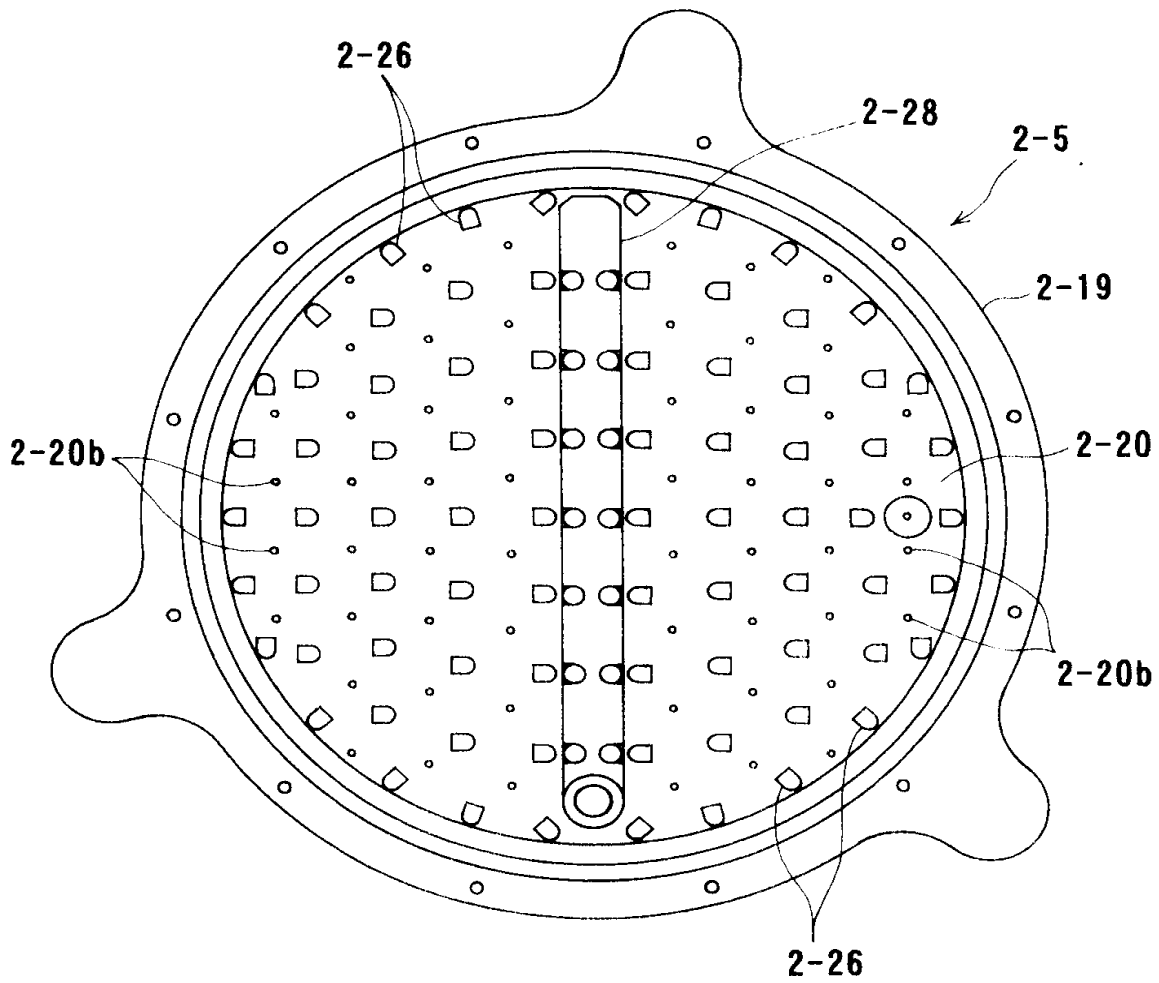


FIG. 46

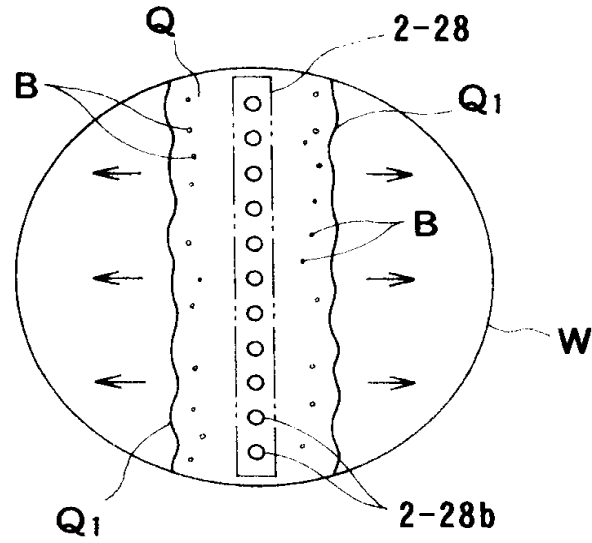


FIG. 47A

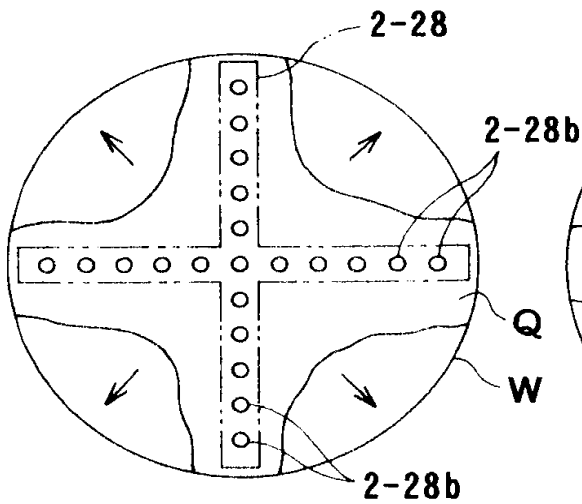


FIG. 47B

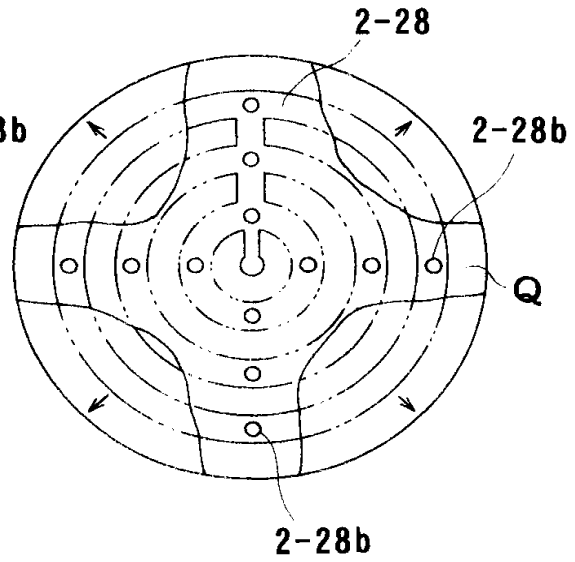


FIG. 48

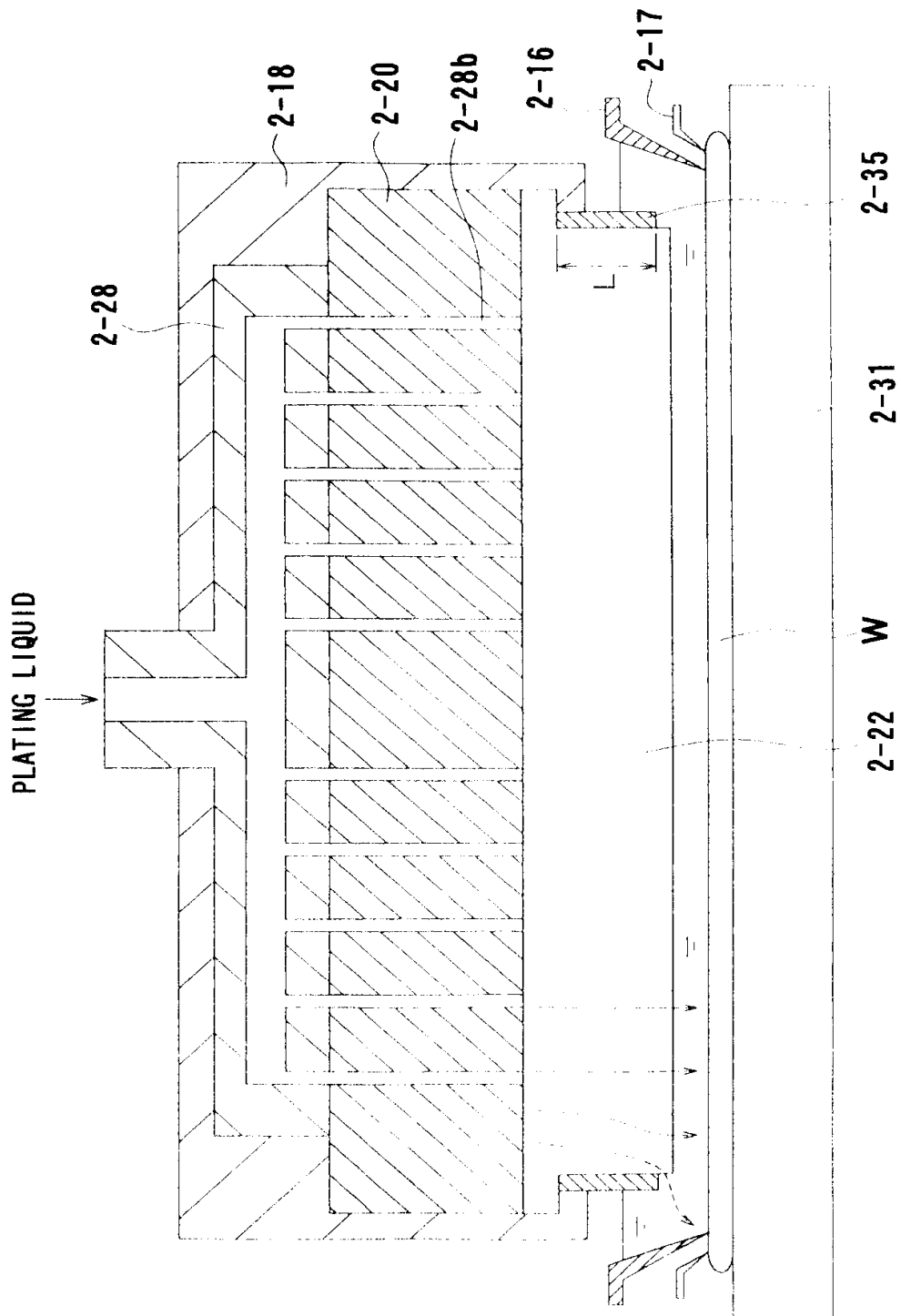


FIG. 49

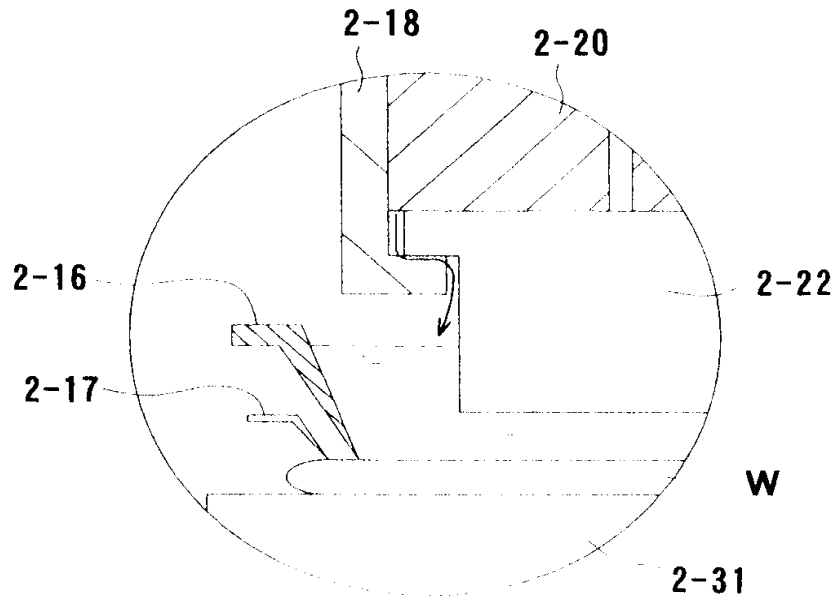


FIG. 51

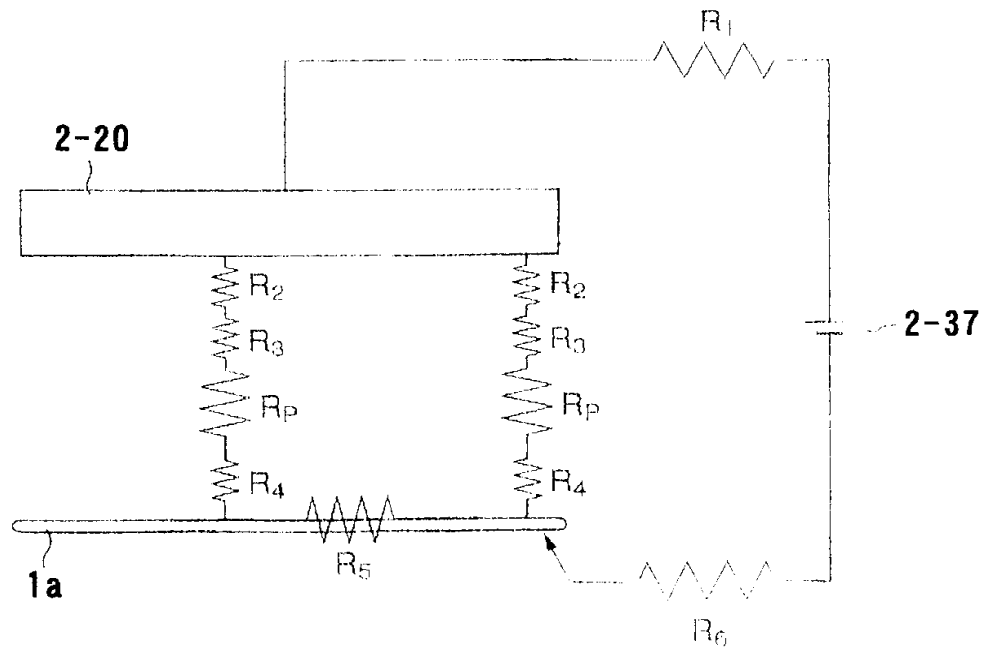


FIG. 50A

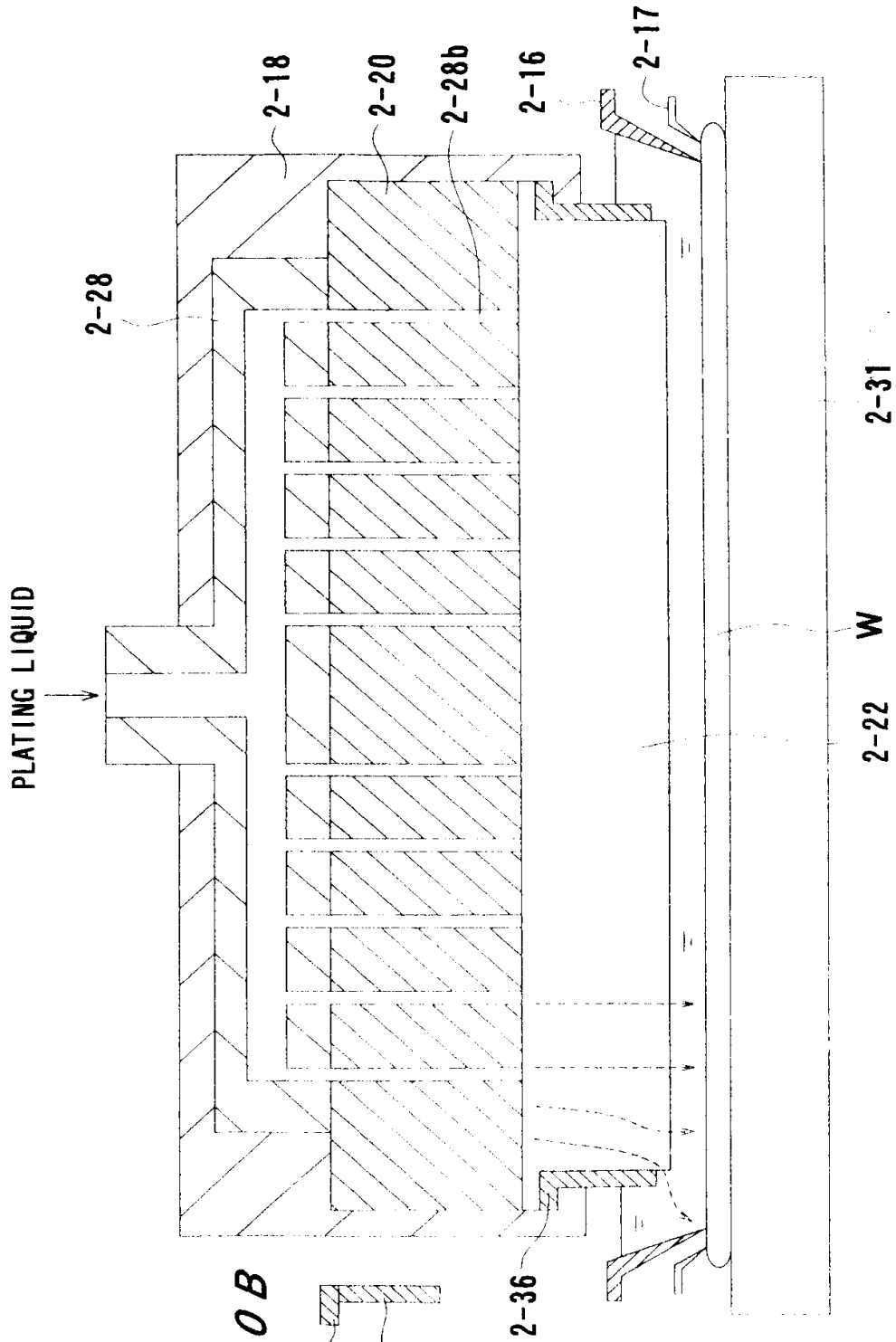


FIG. 50B

